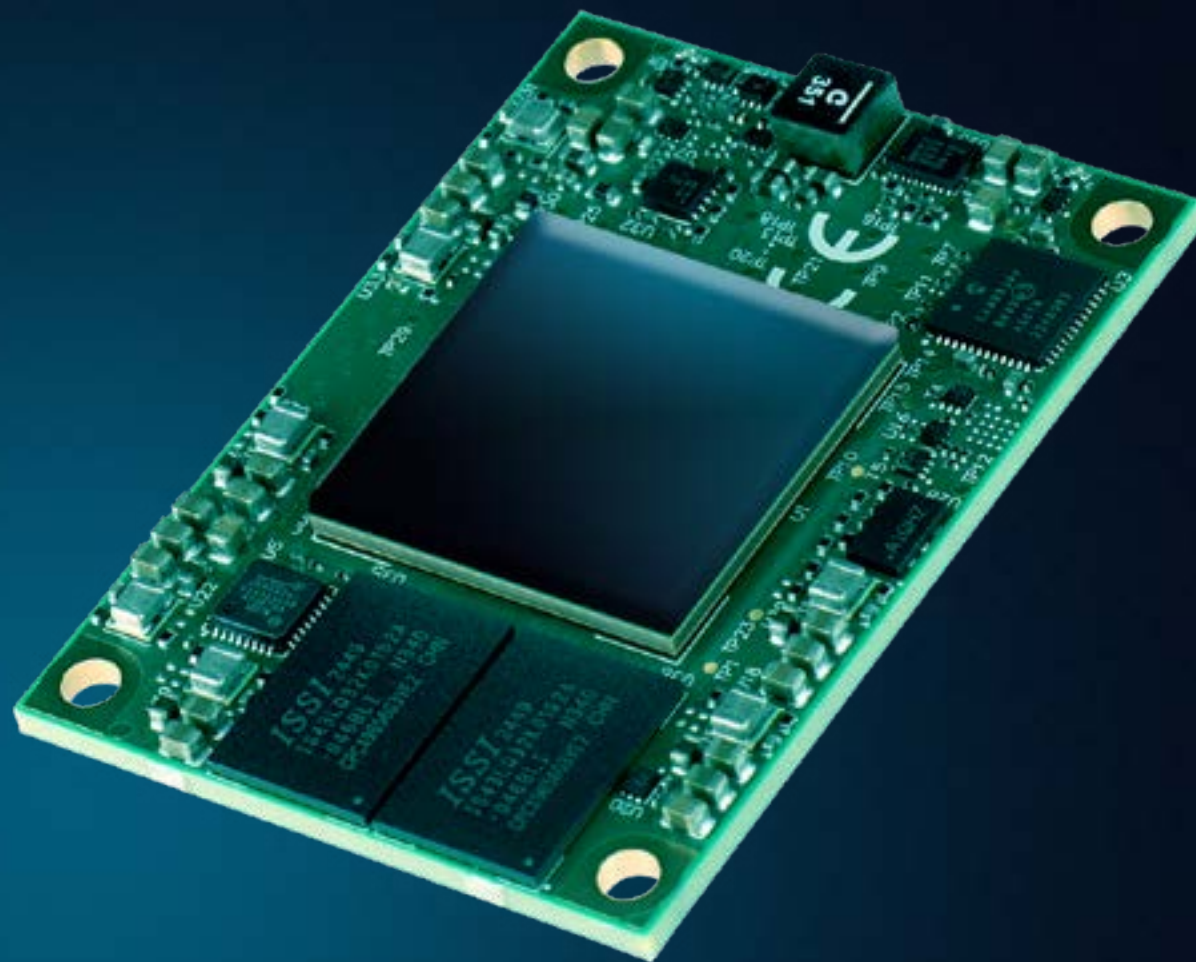




FPGA & SoC. Made in Germany.

Catalogue 2026

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Facts & Figures



Location

Germany

Employees

> 100

Region of Focus

EMEA, NA

Founded

2002

Total Modules

> 600k

Vertical Markets

ALL

Unique Modules

500+

AMD

Embedded
Partner
Program

PREMIER

altera™ **solution**
acceleration partner

Historie

1992

Foundation as
engineering firm
(sole proprietorship)

2002

Change to
Trenz Electronic
GmbH

2007

Xilinx Certified
Partner

2011

Relocation &
expansion of
capacities

2014

Establishment of
Inhouse Production:
1st SMD Assembly Machine

ISO 9001 & 14001
certification

2018
Expansion to
2nd location

2020
Relocation to
current location

2021
MEGA 65

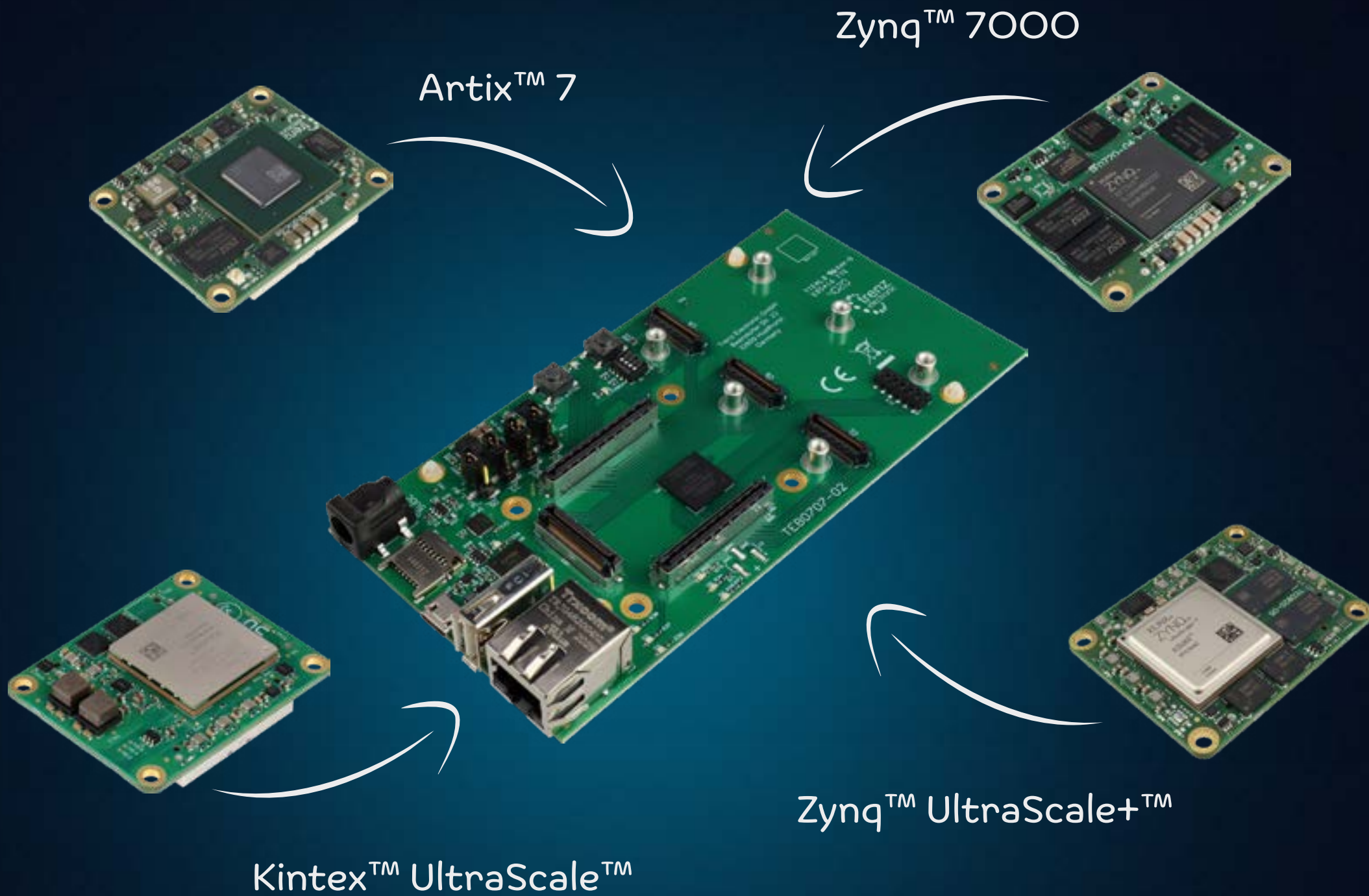
2023
X-ray
machine

2024
Selective solde-
ring machine

2025
Modernisation
of the building

A series of approximately 15 light blue, hand-drawn style ovals are arranged in a loose circular pattern around the central text. They vary in size and orientation, creating a decorative frame.

Families
with many children.



4 x 5 cm Modules | Artix™ 7 / Zynq™ 7000



	TE0710	TE0711	TE0712	TE0713
Device Family	Artix™ 7	Artix™ 7	Artix™ 7	Artix™ 7
Device List	35T, 50T, 75T, 100T	35T, 50T, 75T, 100T	75T, 100T, 200T (with restrictions: 15T, 35T, 50T)	75T, 100T, 200T (with restrictions: 15T, 35T, 50T)
Form Factor	4 x 5 cm	4 x 5 cm	4 x 5 cm	4 x 5 cm
Connectors	2x Samtec LSHM	3x Samtec LSHM	3x Samtec LSHM	3x Samtec LSHM
Processing System	MicroBlaze	MicroBlaze	MicroBlaze	MicroBlaze
max. SDRAM	512 MB DDR3	-	1 GB DDR3	1 GB DDR3L
Flash	32 MB	32 MB	32 MB	32 MB
EEPROM	-	-	x MAC	-
eMMC	-	-	-	-
Oscillator	100 MHz	100 MHz	-	-
Ethernet / USB	2x 100 Mbit	USB 2.0 UART/FIFO	100 Mbit	USB 3.0
Total I/Os	112	178	158	152
Gbit Transceivers	-	-	4x GTP	4x GTP
Other Features	JTAG, user LED, single supply	4 LEDs, single supply	Programmable clock generator, single supply	Programmable clock generator, single supply

4 x 5 cm Modules | Kintex™ 7 / Kintex™ UltraScale™

AMD
ZYNQ
7000



AMD
ZYNQ
7000



AMD
KINTEX™ 7



AMD
KINTEX
UltraScale



	TE0715	TE0720	TE0741	TE0841
Device Family	Zynq™ 7000	Zynq™ 7000	Kintex™ 7	Kintex™ UltraScale™
Device List	Z-7015, Z-7030, Z-7012S	Z-7015, Z-7030, Z-7012S	70T, 160T, 325T, 410T	KU035, KU040
Form Factor	4 x 5 cm	4 x 5 cm	4 x 5 cm	4 x 5 cm
Connectors	3x Samtec LSHM	3x Samtec LSHM	3x Samtec LSHM	3x Samtec LSHM
Processing System	2x Cortex A9	2x Cortex A9	MicroBlaze	MicroBlaze
max. SDRAM	1 GB DDR3	1 GB DDR3	-	2 GB DDR4
Flash	32 MB	64 MB	32 MB	64 MB
EEPROM	1x MAC	1x MAC	-	-
eMMC	-	32 GB	-	-
Oscillator	-	-	-	-
Ethernet / USB	1 Gbit / USB 2.0	1 Gbit / USB 2.0	-	1 Gbit
Total I/Os	132 + 14 MIO	152 + 14 MIO	144	144
Gbit Transceivers	Z-7015: 4x GTP, Z-7030: 4x GTX	-	8x MGT	8x GTH
Other Features	Programmable clock generator, real time clock, single supply	Real time clock, 2k serial EEPROM, 3 user LEDs, single supply	Programmable clock generator, single supply	Programmable clock generator, single supply

4 x 5 cm Modules | Zynq™ UltraScale+™ / Spartan™ UltraScale+™



	TE0820	TE0821	TE0823	TE0873 (preliminary)
Device Family	Zynq™ UltraScale+™	Zynq™ UltraScale+™	Zynq™ UltraScale+™	Spartan™ UltraScale+™
Device List	ZU2CG-ZU5CG, ZU2EG-ZU5EG, ZU4EV, ZU5EV	ZU2CG-ZU5CG, ZU2EG-ZU5EG, ZU4EV, ZU5EV	ZU2CG-ZU5CG, ZU2EG-ZU5EG, ZU4EV, ZU5EV	XCSU35P Optional: SU10P, SU25P, SU50P
Form Factor	4 x 5 cm	4 x 5 cm	4 x 5 cm	4 x 5 cm
Connectors	3x Samtec LSHM	3x Samtec LSHM	3x Samtec LSHM	3x Samtec LSHM
Processing System	Up to 4x Cortex A53 + 2x Cortex R5	Up to 4x Cortex A53 + 2x Cortex R5	Up to 4x Cortex A53 + 2x Cortex R5	–
max. SDRAM	4 GB DDR4	4 GB DDR4	2 GB DDR4	–
Flash	128 MB	128 MB	128 MB	256 Mbit QSPI
EEPROM	–	1x MAC	1x MAC	–
eMMC	8 – 64 GB	8 – 64 GB	8 – 64 GB	–
Oscillator	100 MHz	100 MHz	–	100 MHz
Ethernet / USB	1 Gbit / USB 2.0 OTG	1 Gbit / USB 2.0 OTG	1 Gbit / USB 2.0 OTG	USB 3.0
Total I/Os	132 + 14 MIO	34 HP, 96 HD + 14 MIO	132 HP + 14 MIO	178
Gbit Transceivers	4x PS GTR	4x PS GTR	4 x PS GTR	–
Other Features	GPU/VCU depending on device, programmable clock generator, single supply	GPU/VCU depending on device, programmable clock generator, single supply	GPU/VCU depending on device, programmable clock generator, single supply	LEDs, single supply

4 x 5 cm Modules | PolarFire® / GateMate



	TEM0007	TEG2000
Device Family	PolarFire®	Cologne Chip
Device List	MPFS025T, MPFS095T, MPFS160T, MPFS250T	GateMate CCGM1A1
Form Factor	4 x 5 cm	4 x 5 cm
Connectors	3x Samtec LSHM	2x 100-Pin Razor Beam B2B connector
Processing System	-	-
max. SDRAM	1 GB LPDDR4	-
Flash	64 MB	16 MB QSPI
EEPROM	1x MAC	-
eMMC	-	-
Oscillator	-	25 MHz clock oscillator
Ethernet / USB	1 Gbit / USB 2.0	1 Gbit / USB 2.0
Total I/Os	HSIO: 34*; GPIO: 84; MSIO: 14	152 + 14 MIO
Gbit Transceivers	4 + 1	-
Other Features	On-Board DC-DC converter, *highly dependant on used SoC	level shifters, power supply



MPSoC Modules | Zynq™ UltraScale+™



	TE0803 / TE0813	TE0807 / TE0817	TE0808 / TE0818	TE0825
Device Family	Zynq™ UltraScale+™	Zynq™ UltraScale+™	Zynq™ UltraScale+™	Zynq™ UltraScale+™
Device List	ZU1CG-ZU5CG, ZU1EG-ZU5EG, ZU4EV, ZU5EV	ZU4CG-ZU7CG, ZU4EG-ZU7EG, ZU4EV-ZU7EV	ZU6CG, ZU9CG, ZU6EG, ZU9EG, ZU15EG	ZU2, ZU3, ZU4, ZU5
Form Factor	5.2 x 7.6 cm	5.2 x 7.6 cm	5.2 x 7.6 cm	5.4 x 7 cm
Connectors	4x Samtec ST5 / 4x Samtec ADM6	4x Samtec ST5 / 4x Samtec ADM6	4x Samtec ST5 / 4x Samtec ADM6	2x Samtec ADM6, 1x Samtec UMPT
Processing System	Up to 4x Cortex A53 + 2x Cortex R5	Up to 4x Cortex A53 + 2x Cortex R5	Up to 4x Cortex A53 + 2x Cortex R5	Up to 4x Cortex A53 + 2x Cortex R5
max. SDRAM	8 GB DDR4	8 GB DDR4	8 GB DDR4	8 GB DDR4 with EEC
Flash	2x 64 MB	2x 64 MB	128 MB	2x 64 MB
EEPROM	MAC Address	MAC Address	MAC Address	64 kByte, 2x with MAC Address
eMMC	-	-	-	-
Oscillator	100 MHz	100 MHz	-	✓
Ethernet / USB	1 Gbit / USB 2.0 OTG	1 Gbit / USB 2.0 OTG	1 Gbit / USB 2.0 OTG	2x 1 Gbit / -
Total I/Os	204 + 65 MIO	204 + 65 MIO	204 + 65 MIO	136 PL HP + 88 PL HD, 57 PS MIO
Gbit Transceivers	4x PS GTR, 4x PL GTH (ZU4 + ZU5 only)	4x GTR, 16 x GTH	4x GTR, 16x GTH	4x GTR, 4x GTH
Other Features	GPU/VCU depending on device, programmable clock generator, single supply	GPU/VCU depending on device, programmable clock generator, single supply	GPU/VCU depending on device, programmable clock generator, single supply	Real time clock

AMD
ZYNQ
UltraScale+



AMD
ZYNQ
UltraScale+



AMD
ZYNQ
UltraScale+



	TE0860	TE0861	AM0010
Device Family	Zynq™ UltraScale+™	Zynq™ UltraScale+™	Zynq™ UltraScale+™
Device List	ZU4, ZU5, ZU7, CG, EG, EV	ZU6 / ZU9 / ZU15	ZU1CG-ZU5CG, ZU1EG-ZU5EG, ZU4EV, ZU5EV
Form Factor	5.5 x 7.6 cm	5.5 x 7.4 cm	4 x 5.6 cm
Connectors	2x Samtec ADM6	3x Samtec ADM6	2x Samtec ADM6
Processing System	Up to 4x Cortex A53 + 2x Cortex R5	Up to 4x Cortex A53 + 2x Cortex R5	Up to 4x Cortex A53 + 2x Cortex R5
max. SDRAM	8 GB DDR4 64-bit (PS) with ECC; 4GB DDR4 32-bit (PL)	8 GB DDR4 72-bit (PS) with EEC	8 GB DDR4 64-bit with ECC
Flash	Up to 512 MB QSPI	Up to 512 MB QSPI	128 MB
EEPROM	2x MAC Address	2x MAC Address	MAC Address
eMMC	Up to 64 GByte eMMC (Boot possible)	Up to 64 GByte eMMC (Boot possible)	4 – 64 GB
Oscillator	✓	✓	–
Ethernet / USB	2x 1 Gbit / USB 2.0 OTG	2x 1 Gbit / USB 2.0 OTG	1 Gbit / USB 2.0 OTG
Total I/Os	48 PL HD + 52 PL HP, 14 MIO + I2C	HP Banks: 156 SE + HD Banks: 48 SE, 12 MIO + I2C	204 PL, 22 MIO
Gbit Transceivers	4x GTR, 16x GTH	4x GTR, 16x GTH	4x GTR, 4x GTH
Other Features	Single 5 V ... 12 V power input	Single 5 V ... 12 V power input	Optional HyperRAM, security controller, Crypto Authentication

TE0878 AMD Spartan™ UltraScale+™

NEW

SoC

- AMD Spartan UltraScale+
- FPGA: XCSU200P-1SBVA1024I
- Possible variants: SU65P, SU100P, SU150P, SU200P

Memory

- 1x QSPI Flash
- 1x LPDDR5 32 bit

On-Board Peripherals

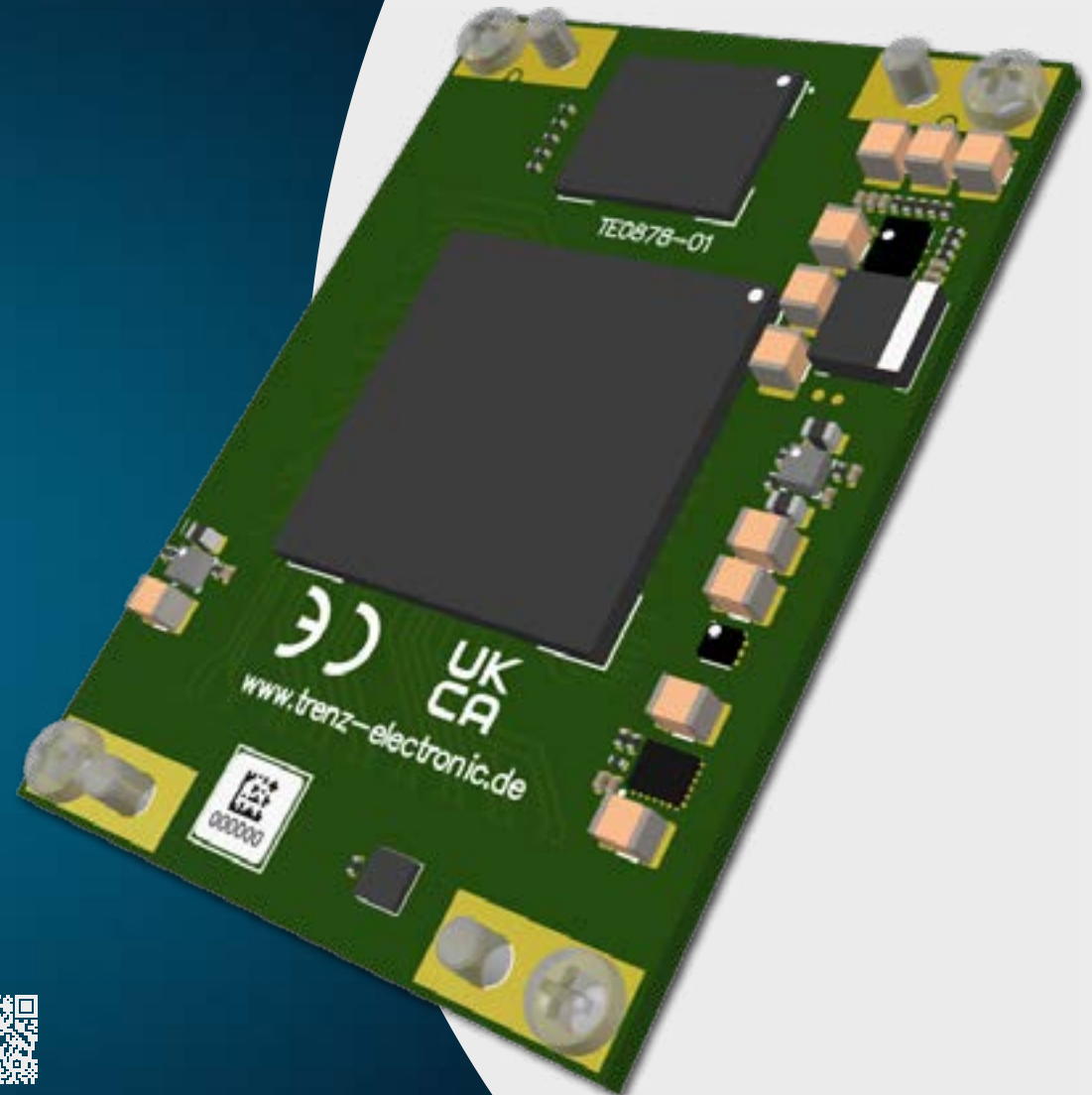
- Clock oscillator
- 4x B2B Connectors Samtec ADM6

IO Resources

- 8x GTH MGT IO
- 66x SE (33x differential) PL XP5IO
- 294x SE (147x differential) PL HD IO
- 104x SE (52x differential) PL HP IO

Dimension

- 55 x 74 mm



AMD
SPARTAN
UltraScale+

click
or
scan





	TE0835	TE0836
Device Family	Zynq™ UltraScale+™	Zynq™ UltraScale+™
Device List	ZU25, ZU27, ZU28, ZU43, ZU47, ZU48	ZU25, ZU27, ZU28, ZU42, ZU43, ZU47, ZU48
Form Factor	6.5 x 9 cm	6.5 x 9 cm
Connectors	2x Samtec ST5	2x Samtec ADM6
Processing System	Up to 4x Cortex A53 + 2x Cortex R5	Up to 4x Cortex A53 + 2x Cortex R5
max. SDRAM	4 GB DDR4	4 GB DDR4
Flash	128 MB	128 MB
EEPROM	MAC Address	MAC Address
Temperature	Extended / Industrial	Extended / Industrial
Oscillator	FPGA System Oscillator	FPGA System Oscillator
Ethernet / USB	1 Gbit / USB 2.0 OTG	1 Gbit / USB 2.0
Total I/Os	40x I/O 20 LVDS + 32 MIO	68x I/O 20 LVDS + 33 MIO
Gbit Transceivers	8x GTY, 4 x GTR	8x GTY, 4 x GTR
Other Features	4x User LEDs, RF-ADCs, RF-DACs, Crypto Authentication	4x User LEDs, RF-ADCs, RF-DACs, Crypto Authentication

AMD
VERSAL
AI Edge

NEW

AMD
VERSAL
AI Edge

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or
scan



	TE0965	TE0955
Device Family	Versal™ AI Edge Gen2	Versal™ AI Edge
Device List	SSVA2112 possible variants	VE2002, VE2102, VE2202, VE2302, VM1102
Form Factor	7.5 x 9 cm	4 x 5.6 cm (Andromeda)
Connectors	2x Samtec ADF/ADM, 1x Samtec APM6/APF6	2x Samtec ADM
Processing System	–	2x Cortex A72, 2x Cortex R5F
max. SDRAM	4x 32-bit LPDDR5	8 GB LPDDR4 (2x 32 Gbit)
Flash	OSPI Flash	256 MB OSPI
EEPROM	1x MAC, 1x User Data	MAC Address
eMMC	–	32 GB
Clock	10 Output Clock Generator	Clocks for PS / PHY / DDR4 / PL
Ethernet / USB	1 Gbit / USB 2.0 OTG	1 Gbit / USB 2.0
Total I/Os	X5IO: 62 diff; HDIO: 22 diff; MIO	100
Gbit Transceivers	PL: 20 x GTYP; PS: 4x GTYP, 4x PS-GTR	8x GTYP
Other Features	Connector-based Harmonized FPGA Module: oHFM.c-L	–

SoC Modules | Zynq™ 7000



	TE0716	TE0724	TE0728
Device Family	Zynq™ 7000	Zynq™ 7000	Zynq™ 7000
Device List	Z-7020	Z-7010, Z-7020	XA7Z020 (automotive FPGA)
Form Factor	4.5 x 6.5 cm	4 x 6 cm	6 x 6 cm
Connectors	2x FCI Bergstak	1x Samtec ST5	3x Samtec SEM
Processing System	2x Cortex A9	2x Cortex A9	–
max. SDRAM	1 GB DDR3L	1 GB DDR3L	512 MB DDR3
Flash	32 MB	64 MB	16 MB
EEPROM	MAC Address	MAC Address	2 KB
eMMC	–	–	–
Oscillator	✓	100 MHz	–
Ethernet / USB	1 Gbit / USB 2.0	1 Gbit	2x 100 Mbit
Total I/Os	120x HR PL	PL: 80, PS: 20	124 + 42 MIO
Gbit Transceivers	2x PS MIO	–	–
Other Features	10x 12-bit low power SAR ADCs up to 2 MSPS, USB2.0 to UART/JTAG interface	CAN, single supply, 3x LED (1x PS, 2x PL)	Automotive, real time clock, CAN, 12 V power supply

AMD
ZYNQ
7000



AMD
ZYNQ
7000



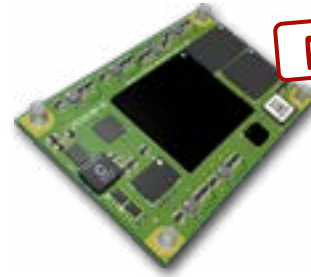
AMD
ZYNQ
7000



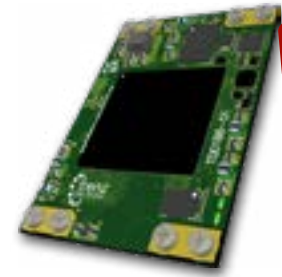
	TE0729	TE0745	TE0782
Device Family	Zynq™ 7000	Zynq™ 7000	Zynq™ 7000
Device List	Z-7020	Z-7030, Z-7035, Z-7045	Z-7035, Z-7045, Z-7100
Form Factor	5.2 x 7.6 cm	5.2 x 7.6 cm	8.5 x 8.5 cm
Connectors	2x Samtec BTE	3x Samtec ST5	3x Samtec QTH
Processing System	2x Cortex A9	2x Cortex A9	2x Cortex A9
max. SDRAM	512 MB DDR3	1 GB DDR3L	1 GB DDR3
Flash	32 MB	64 MB	32 MB
EEPROM	3x MAC Address	MAC Address	2x MAC Address
eMMC	4 – 64 GB	–	4 – 64 GB
Oscillator	✓	–	✓
Ethernet / USB	2x 100 Mbit, 1 Gbit / USB 2.0 OTG	1 Gbit / USB 2.0 OTG	2x 1 Gbit / 2x USB 2.0 OTG
Total I/Os	136 + 14 MIO	250 + 6 MIO	250 + 2 MIO
Gbit Transceivers	–	8x GTX	16x GTX
Other Features	Real time clock	Real time clock, single supply	Programmable clock generator, real time clock

altera™

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or
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NEW



NEW

	TEI0006	TEI0135	TEI0186
Device Family	Cyclone® 10 GX	Agilex™ 3	Agilex™ 5
Device List	10CX220, 10CX150, 10CX105	A3C 100, 135	A5E 013A, 028A, 008B, 013B, 028B (default)
Form Factor	6 x 8 cm	4 x 5.64 cm	5.2 x 7.6 cm
Connectors	3x Samtec ST5	2x Samtec AMD6	3x Samtec ADM6
max. SDRAM	2 GB DDR3L	4 GB LPDDR4	4 GB LPDDR4
Flash	256 MB	up to 128 MB QSPI	256 MB
EEPROM	MAC Address	2x MAC Address	1x MAC Address, 1x 128 Kbit
eMMC	-	up to 64 GB	8 – 64 GB
Clock	-	25 MHz (SDM), 25 MHz (HPS), 200 MHz (LPDDR4), diff. CLKs from B2B	Clocks for LPDDR4 SDRAM, GigE PHY, USB PHY, SDM FPGA
Ethernet / USB	1 Gbit / -	1 Gbit / USB 2.0 (Support USB3.1)	1 Gbit / USB 2.0 (Support USB3.1)
Total I/Os	226	• HSIO: 24 differential / 48 single ended + MIPI D-PHY (4 Data+ CLK + REF CLK) • HVIO: 120 single ended • HPS: 12 I/O (SD3.0/eMMC, UART, I2C, I3C etc.)	• MGT: up to 12 x transceivers (up to 28 Gbit/s) • HSIO: 96 differential / 192 single ended + MIPI D-PHY (4 Data+ CLK + REF CLK) • HVIO: 200 single ended • HPS IO: 19 I/O (SDIO, UART, I2C, I3C, GPIOs)
Gbit Transceivers	-	4 (support HIP PCIe x4 Gen3), 12.5 Gbit/s	-
Other Features	MAX® 10 as power sequencer, 4 LEDs, 5 V power supply	5...12 V power supply	TPM2.0, SD3.0 (optional), 5...12 V power supply



	TEI0187	TEI1000
Device Family	Agilex™ 5	Stratix® 10
Device List	A5E 043A, 043B, 052A, 052B, 065A, 065B	GX400, GX650, SX400, SX650
Form Factor	5.2 x 7.6 cm	6 x 8 cm
Connectors	3x Samtec ADM6	3x Samtec ADM6
max. SDRAM	2 GB LPDDR4	2 GB DDR4
Flash	256 MB	64 MB QSPI
EEPROM	1x MAC Address, 1x 128 Kbit	–
eMMC	8 – 64 GB	–
Clock	25 MHz (SDM), 25 MHz (HPS), 2x 200 MHz (LPDDR4), diff. CLKs from B2B	–
Ethernet / USB	1 Gbit / USB 2.0 (Support USB3.1)	–
Total I/Os	331 I/Os, 96 diff. pairs, 19 HPS I/Os	GX: 218 / SX: 296
Gbit Transceivers	8x GTX	18x GTX
Other Features	12 V power supply	MAX® 10 system controller, status & user LEDs, 1.8 & 3.3 V



What Trenz
can do for you?

Development & Manufacturing of FPGA & SoC modules

Full Service

design-in support through to turnkey solutions

- Hard- & Software
- Prototyping
- Series production

Customization

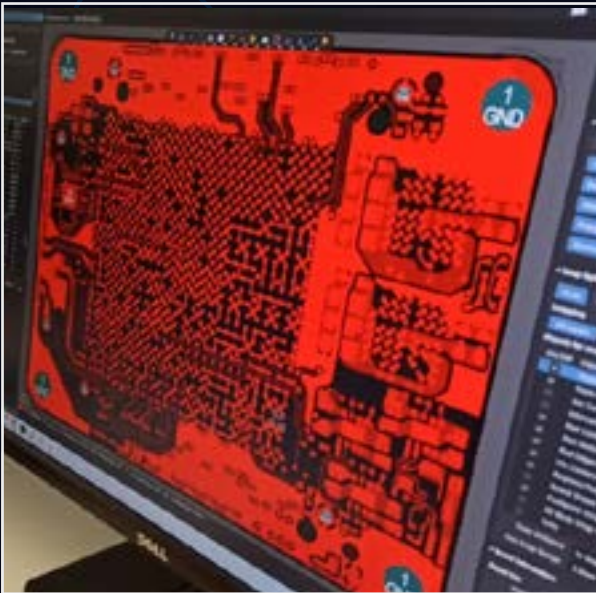
Custom solutions & rapid prototyping

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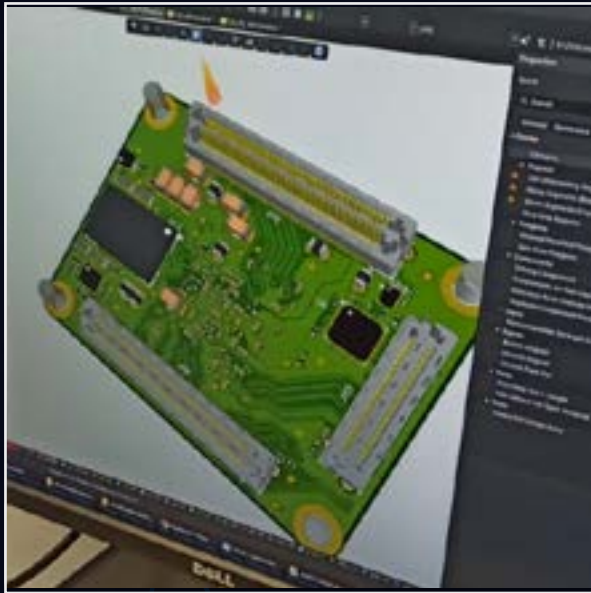
Development

FPGA / SoC Design



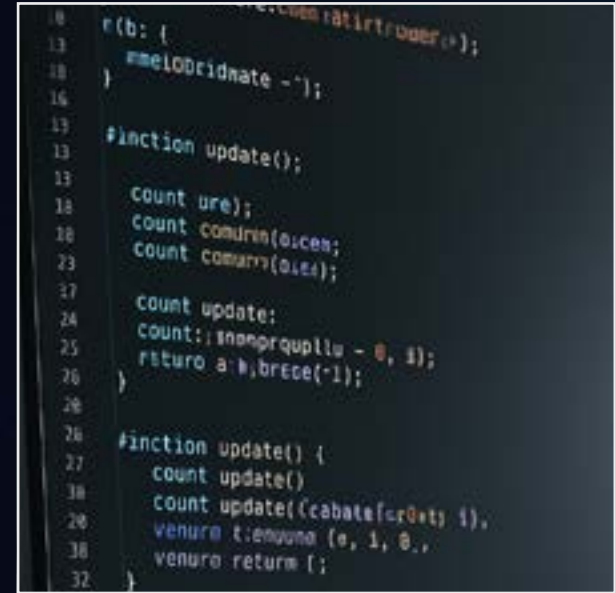
FPGA / HDL Design &
Synthesis

Hardware Development



Schematic Capture &
PCB Layout

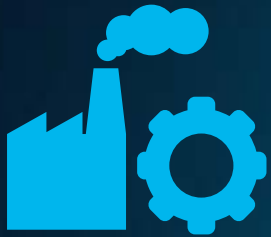
Software Development



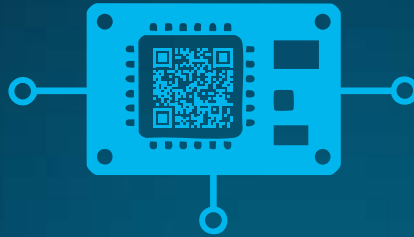
Soft- & Firmware
Development

Inhouse Production

All modules are developed, manufactured & tested in Germany.



Inhouse
Production & Testing



Traceability &
Test concepts



Short lead times &
high availability



9001:2015

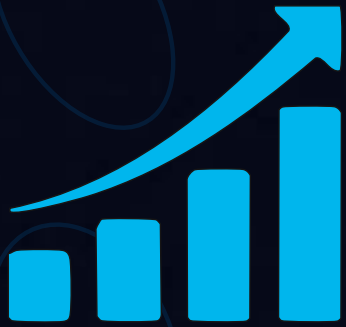
Quality management



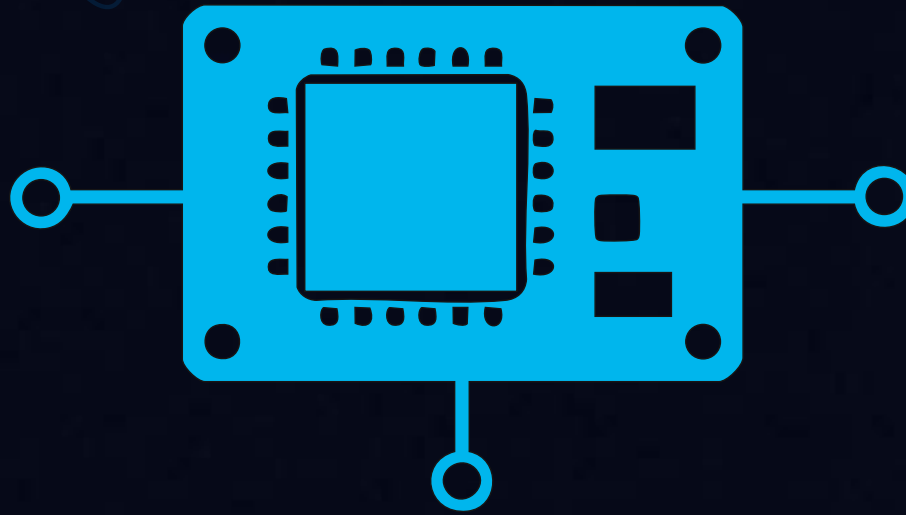
ISO 14001



Assembly Variants



Scalability



No NRE



Cost optimization



High flexibility



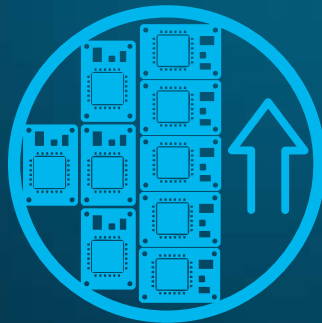
Be future-proof

Customization & Chipdown

Chipdown
from scratch



Assembly of customer-specific modules/boards



Adaptation to quantities



Maker & Low Cost Modules

AMD
ZYNQ
7000

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ZYNQ
7000

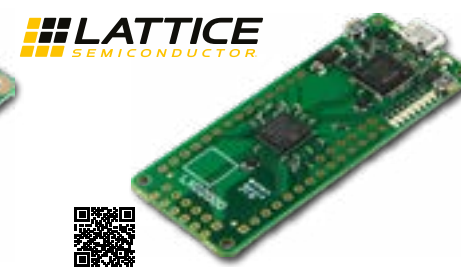
Raspberry Pi 3
compatible



AMD
ZYNQ
7000



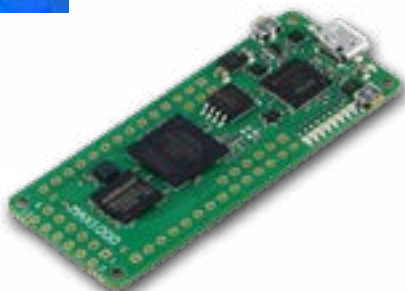
	TE0723 "ArduZynq"	TE0726 "ZynqBerry"	TE0727 "ZynqBerryZero"
Device Family	Zynq™ 7000	Zynq™ 7000	Zynq™ 7000
Device List	Z-7010, Z7007S	Z-7010, Z-7007S	Z-7010
Form Factor	6.9 x 5.3 cm	6.35 x 9.3 cm	3 x 6.5 cm
Connectors	Arduino Pmod headers	40-pin "HAT" headers	40-pin "HAT" headers
Processing System	-	-	-
max. SDRAM	512 MB DDR3L	512 MB DDR3L ECC	512 MB DDR3L
Flash	16 MB	16 MB	16 MB
Ethernet / USB	- / micro USB OTG, micro USB	100 Mbit / 4x USB 2.0	- / 2x micro USB 2.0
Total I/Os	30	26	26 GPIO
Other Features	microSD, FR2232, JTAG/UART/FIFO	DSI display & CSI-2 camera connector, microSD, 3.5 mm audio, HDMI type A	microSD, Mini HDMI type C, CSI-2 camera connector



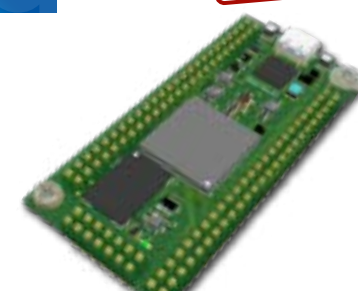
	TE0890 "S7 Mini"	TE0876 "IceZero"	TEL0001 "LXO2000"
Device Family	Spartan™ 7	Lattice ICE40 HX	Lattice XO2
Device List	7S25	iCE40HX	LCMXO2-4000HC
Footprint compatible	7S6, 7S15, 7S50 FTGB-196 devices	-	-
Form Factor	2.7 x 5.2 cm	5.6 x 3.05 cm	2.5 x 6.15 cm
Connectors	-	4x Pmod (DNP by default)	-
max. SDRAM	-	4 Mbit external SRAM	-
HyperRAM DRAM	64 MB	-	-
Flash		8 MB	-
Config PROM	64 MB	-	-
Oscillator	-	100 MHz	100 MHz
Ethernet/USB	-	-	- / USB JTAG, USB serial
Total I/Os	Dual-Pinout DIP-40 / 50mil 80 pin for 32 / 64 FPGA 3.3 V I/Os	-	22 on MKR header, 2 I/O on additional header, optional Pmod header +8
Interfaces	Standard 1x 6 FTDI cable seria	-	-
Other Features	5 V power supply, 23K Logic Cells, 29K Flops, 45 36Kb BRAMs, 80 Mults	3 user LED, supported by fully open source FPGA toolchain	8 LEDs, 2 push buttons, 5 V power supply

Maker & Low Cost Modules

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Arduino MKR
Standard

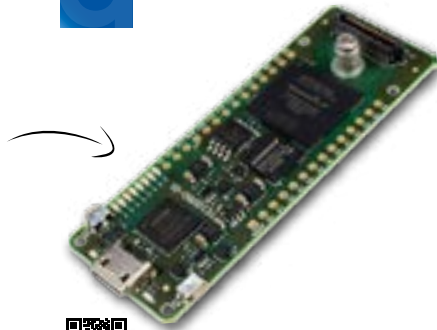


NEW

	TEI0001 "MAX1000"	TEI0003 "CYC1000"	TEI0050	TEI0140
Device Family	MAX® 10	Cyclone® 10	Cyclone® V	Agilex™ 3
Device List	10M02, 10M04, 10M08, 10M16	10CL006, 10CL010, 10CL016, 10CL025	E, A2, A4	A3C 025 (no LPDDR4), 050, 065, 100, 135
Form Factor	2.5 x 6.15 cm	2.5 x 6.15 cm	2.5 x 7.07 cm	3.5 x 7.3 cm
max. SDRAM	64 MB	8 MB	8 MB	2 GB LPDDR4
Flash	8 MB	2 MB	up to 256 MB	up to 128 MB QSPI
On-Board	• 8 or 16 kLE • USB programmer • JTAG / UART over microUSB 2.0 connector • ADC 8x 12 bit • 12 MHz oscillator • optional MEMS oscillator • optional Pmod headers • USB supply • 2 switches • 8x configurable LEDs • 2x status LEDs	• 25 kLE • 21 I/O Arduino MKR compatible headers • LS2DH 3-axis accelero-meter • 2x 14-pin headers providing 23 GPIOs • 1x 3-pin header providing 2 GPIOs • Pmod: 2x 6-pin support • User push button • 8x configurable LEDs • 2x status LEDs	• CRUVI HS • 2x 14 pin header	• Security: TPM2.0 • Clock: 12 MHz (FTDI), 25 MHz (SDM), 200 MHz (LPDDR4) • LEDs: 2x RGB LED, 1x LED • Push Buttons: 1x User • USB Programmer: USB Blaster III (JTAG + UART or FIFO Interface) • 2x 50 pin-header connectors, 1x 14 pin-header connector • 3x EEPROM
Power Supply	5 V power supplied from USB	5 V single supply with on-board voltage regulators	USB-to-JTAG/GPIO-FTDI, User push buttons, LEDs	USB-C: 5 V



Arduino MKR
Standard



	TEI0181	TEM0001 "SMF2000"	TEM0005
Device Family	Agilex™ 5	SmartFusion® 2	SmartFusion® 2
Device List	A5E 008B, 013B, 028B	M2S005, M2S010, M2S025, M2S050, M2S060	M2S005, M2S010, M2S025, M2S050, M2S060
Form Factor	2.5 x 6.15 cm	2.5 x 6.15 cm	3.1 x 5.6 cm
max. SDRAM	128 MB HyperRAM	8 MB	256 MB DDR3
Flash	256 MB QSPI	8 MB	32 MB
On-Board	• USB Blaster III • 3-axis Accelerometer • 2x RGB LED's • 1x LED • 2x DIP Switches • 2x Buttons • 1x CRUVI HS Connector • 1x Arduino MKR Connector • UART via USB Blaster Connector	• 12 MHz system clock • 32.768 kHz auxiliary clock • microUSB 2.0 connector • 31 I/Os (8 I/O 1x Pmod header, 23 I/O 2x 14-pin header)	• 1x Samtec ST5 160 pin • 100 Mbit/s Ethernet PHY • 105 I/Os • EEPROM MAC Address
Power Supply	5 V supply via USB-C Connector	1x 3-pin header for LiveProbes, 9 user LEDs, 1 user push button	Optional crypto authentication, power supply monitor

Compact Modules

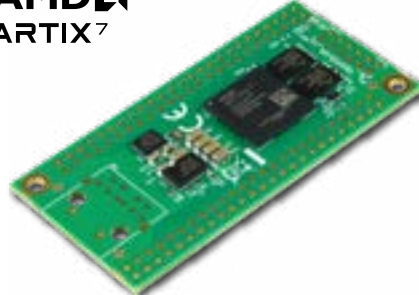
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ARTIX⁷



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	TE0714	TE0725	TE0790 / 0790-L FTDI JTAG Adapter	TEM0009 JTAG USB-Programmer
Device Family	Artix™ 7	Artix™ 7	-	-
Device List	A12, A15, A25, A35, A50	15T, 35T, 50T, 75T, 100T	Lattice X02-256 CPLD	-
Pin Packages	CSG325	CSG324	-	-
Form Factor	3 x 4 cm	3.5 x 7.3 cm	XMOD, M3 mounting hole	1.35 x 2.2 cm
Connectors	2x Samtec LSHM	2x 50-pin headers	mini USB	micro USB, USB 2.0 support 2x 5-pin JTAG header
max. HyperRAM	-	32 MB	-	-
Flash	16 MB	32 MB	-	-
EEPROM	-	16 KB	✓	-
Total I/Os	138 + 5 (QSPI or user I/Os)	87	8 universal I/O pins	-
Gbit Transceivers	4x GTP	-	-	-
Power Supply	3.3 V / 1.8 V configurable voltage (B14)	-	-	0.8 ... 3.6 V
Other Features	5 V power supply, 23K Logic Cells, 29K Flops, 45 36Kb BRAMs, 80 Mults	Optional POF adapter (125/250 Mbit/s)	DCDC converter for supply via USB-power, DIP switch, channel B RS/TX LEDs	Green power-on LED

PCIe FMC Carrier



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	TEF1001	TEF1002	TEF0008 FMC Card
Device Family	Kintex™ 7	-	-
Device List	XC7K160T	-	-
Form Factor	10.66 x 16.76 cm	10.66 x 16.76 cm	6.9 x 8.4 cm
On-Board / Connectors / Interface	- FMC - up to 8 GB DDR3 SO-DIMM Socket SDRAM 32 MB Flash - programmable clock 160 on FMC connector - Gbit Transceivers: 4 on FMC, 4 on PCIe lanes	- LPC FMC - SFP+ - PCIe x1 - SATA with pin 7 power configuration for SATADoM - RJ45 Gbit Ethernet - microUSB to JTAG/UART bridge 2x 8 LVDS (FireFly) - microUSB - microSD card	4 SFP+ 10 Gbit ports for fiber optical SFP modules
Other Features	Vita 57.1 FMC HPC slot, 200 MHz low jitter LVDS oscillator	MAX® 10 CPLD, 4x LED, module reset button, 10x user dip switch	Low jitter programmable clock generator, 3.3 ... 1.8 V DCDC converter, 128 Kbit EEPROM, status LED

Development & Evaluation Boards

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	TE0950 Versal™ AI Edge Evalboard	TE0802 MPSoC Development Board	TEI0009 C10LP RefKit Development Board
Device Family	Versal™ AI Edge	Zynq™ UltraScale+™	Cyclone® 10 LP
Device List	VE2302	ZU1CG, ZU2CG	10CL016, 10CL025, 10CL040, 10CL055, 10CL080
Form Factor	15 x 12 cm	10 x 10 cm	9.5 x 11 cm
max. SDRAM	8 GB DDR4	2 GB LPDDR4	512 Mbit / 128 Mbit HyperRAM
Flash	2x 64 MB QSPI	32 MB	Up to 512 Mbit QSPI (user Flash) / 32 Mbit
EEPROM	MAC Address	MAC Address	-
eMMC	32 GB	-	-
Connectors	zQSFP, CRUVI 2x HS / 2x LS, CSI-2, FMC	-	QSE (for LVDS), Pmod, Arduino, SMA
Ethernet / USB	1 Gbit / USB 2.0 JTAG/UART	1 Gbit / USB 3.0 Type A	2x 10/100 / USB 2.0
Total I/Os	-	2 Pmod connectors (User I/O)	-
Other Features	Artix™ 7 FPGA as configurable levelshifter, 3x clock (1x PL, 2x GTs), 2 LEDs, push button, dip switches, reset button	3.5 mm audio (PWM), USB JTAG/UART microUSB, microSD, M2 PCIe SSD support, display, 5 V power supply	Integrated USB programmer ²



	TEIB0006 Development Carrier Board
Supported SoM	TEI0006
Form Factor	15 x 12 cm
RAM / Storage	EEPROM
On-Board	• 3x LEDs (power, 2x user) • 3x I/O expanders • 3x push buttons (2x user, system controller config) • DIP switch
Interface	• 2x SFP connectors • 3x Samtec ST5 B2B connectors • FMC HPC connector (10x transceiver, 34x LVDS/LA, 10x LVDS/HA) • Gigabit Ethernet connector • USB 2.0 microUSB (JTAG/UART) • USB 3.0 type C
Power supply	12 V



	TEI0185 Agilex™ 5E Development Board
Device	Agilex™ A5ED065BB32AE4SO0
Form Factor	16 x 25 cm
On-Board	• 2x Ethernet PHY • HDMI Transmitter • USB-to-UART FTDI • 8 channel ADC/DAC • PLL clock • Oscillator • 2x EEPROM with MAC Address • 128 Kbit EEPROM • 2x Temperature sensor • Fan Speed controller • 4x RGB LED • 2x User LED • 4x User push button • 4x DIP switch
Interface	• PCIe x4 (B2B) • TEI0004 connector (B2B) • FMC+ (B2B) • CRUVI (2x HS, 2x LS) • 2x Gigabit Ethernet • HDMI • 4x USB connector • 2x zSFP+ connector • SD card connector • 3x I2C connector • Fan connector
Power supply	12 V

UltraRack+ Board

The TEB0911 UltraRack+ module from Trenz Electronic is a high-performance platform designed for building scalable and reliable computing systems for industrial, telecommunications, and scientific applications.

At the heart of the module is the AMD Zynq™ UltraScale+™ ZU9EG MPSoC, combining powerful processor cores with programmable logic to deliver maximum flexibility for implementing complex data-processing algorithms. For configuration and user data storage, the board includes two 64 MB Flash memories and 8 GByte eMMC, while 8 GB of DDR4 SO-DIMM with a 72-bit data bus ensures high bandwidth and reliable memory operation.

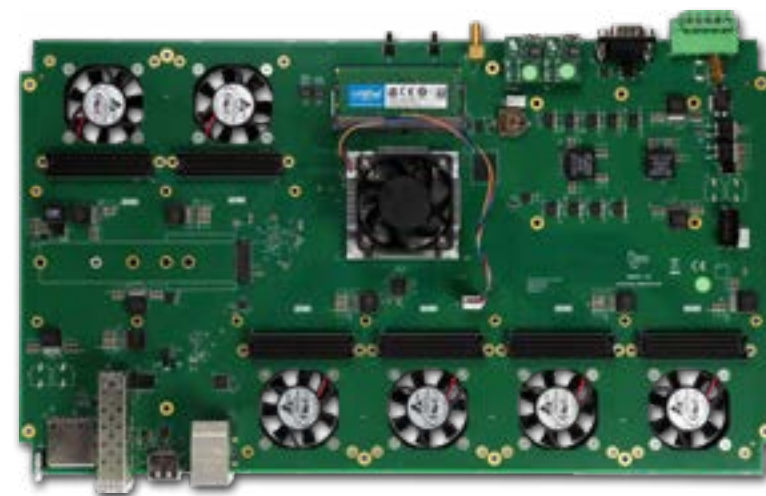
A key advantage of the TEB0911 is its support for up to six VITA™ 57.1 FMC™ modules, each of which can be individually cooled. High-speed connectivity to the MPSoC is provided via GTH MGT transceivers, differential LVDS lines, and low-speed CMOS signals, making the board an ideal foundation for data acquisition and processing systems.

The board features a comprehensive set of interfaces for integration with external devices, including 2x USB 3.0, 2x SFP+, and Gigabit Ethernet, as well as CAN and UART for low-speed communication. SD card boot support, video output via DisplayPort, and an M.2 connector (PCIe x1) for SSDs or other expansion modules significantly extend system functionality without the need for additional hardware.

To support precise timing and synchronization, the module is equipped with two programmable clock generators. Reliable and stable operation is ensured by a combination of switching and linear power supplies, while an onboard CPLD-based system controller acts as an I/O expander and manages key operational modes of the module.

The TEB0911 UltraRack+ is designed for installation in a 19-inch chassis, making it an optimal choice for rack-mount solutions that require high computing density, modularity, and industrial application.

All parts are at least extended temperature range of 0°C to +85°C. The module operating temperature range depends on customer design and cooling solution. Please contact us for options.

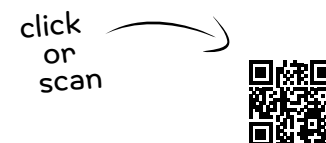


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	TEB0911	
Device Family	Zynq™ UltraScale+™	
Device List	ZU6, ZU9, ZU15	
Form Factor	40.6 x 23.43 cm	
On-Board	• 64-bit DDR4 SODIMM (PS connected) • M2 PCIe SSD (1-Lane) • eMMC (bootable) • 2 x 64 MByte Dual QSPI Flash (bootable)	• System controller (LCMXO2-7000HC) - Power sequencing - IO expander • Configurable PLLs - GTH/GTP reference CLKs
Front Panel	• 4 x FMC - GTH per FMC - 68 ZynqMP PL IIO per FMC • DisplayPort (2-lanes)	• RJ45 ETH + Dual USB3 combo • Dual Stack SFP+ • SD (bootable) • Status LEDs
Back Panel	• 2 x FMC - 4/2 GTH - 12 ZynqMP PL IO per FMC • 56 SC IO	• USB JTAG/UART ZynqMP • USB JTAG/GPIO FMC • CAN FD (DB9 connector) • SMA (external CLK)
Power Supply	5-pin 24 V connector	

DesignWare® ARC® EM Software Development Board



The DesignWare® ARC® EM Software Development Platform is a flexible platform for rapid software development on ARC EM processors and subsystems. It is intended to accelerate software development and debug of ARC EM processor-based systems for a wide range of ultra-low power embedded applications such as IoT, sensor fusion, and voice applications. It includes an FPGA-based hardware board with commonly used peripherals and interfaces for extensibility. Downloadable platform packages containing different hardware configurations enable the board to be programmed with different ARC EM processors and subsystems. The packages also contain the necessary software configuration information for the toolchain and embARC Open Software Platform.

The development platform is supported by Synopsys' MetaWare Development Tool Kit, which includes a compiler, debugger and libraries optimized for maximum performance with minimal code size. The embARC Open Software Platform (OSP), available online from embarc.org, gives developers online access to device drivers, FreeRTOS, middleware and examples that enables them to quickly start software development for their ARC-based embedded systems.

Each hardware configuration includes an ARC EM processor and subsystem with access to 16 MB of PSRAM, 16 MB of SPI Flash and a wide range of peripherals such Audio Line In/Out, UART, SPI, I2C, and ADC. A 9-D motion sensor enable fast development of IoT applications. Two digital MEMs micro-phones can also be used for the development of voice applications. The hardware is extensible using the popular Arduino® interface and extension is also possible with Digilent Pmod Interfaces, mikroBUS headers and a 50-pin header. Debug and trace are handled with USB/JTAG interfaces and a NEXUS interface for ARC Real-Time Trace (RTT). The board includes a micro-SD card slot for loading application software.

	TEC0089	
Device Family	Kintex™ 7	
Device List	XC7K325T-2FBG676C	
Form Factor	7.25 x 13.7 cm	
Flash	32 MB QSPI	
RAM	2x 8 MB PSRAM	
On-Board / Connectors / Interface	• Arduino compatible pin headers • microUSB compatible pin headers • 3x Pmod compatible pin headers • 50 pin header 2.54 mm • Mictor debug connector • 10 pin debug connector 2 mm • microSD card socket	• 3-axis gyroscope, 3-axis accelerometer, 3-axis magnetometer • Stereo audio codec MAX9880A • 2x PDM microphones • 2x 3.5 mm RCA audio jacks (input/output) • 100 MHz user clock oscillator SiT8008 • Status LEDs, power LED
Power Supply	12 V (seperately included in the scope of delivery)	

What is CRUVI?

A short overview.



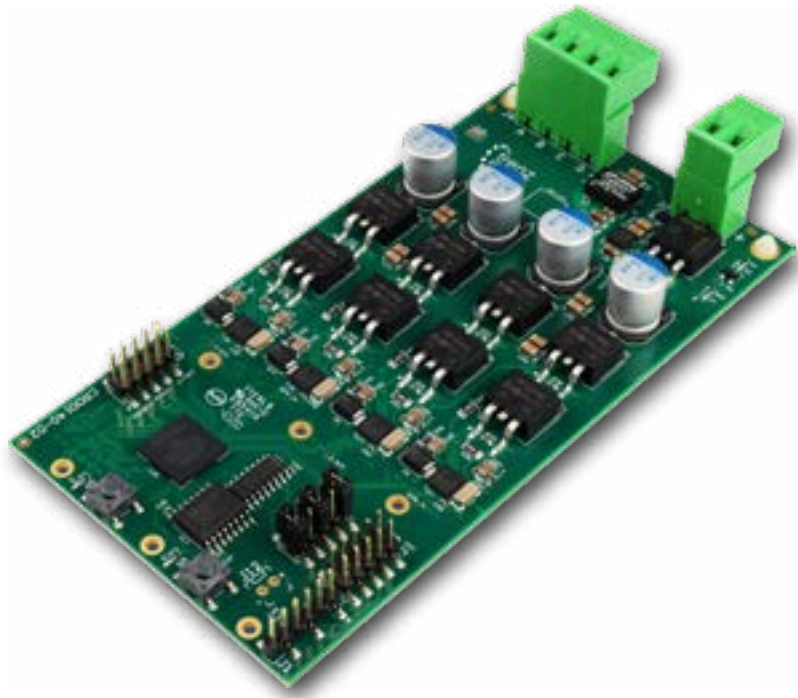


The word CRUVI is a combination of the Estonian word "KRUVI" for screw and the letter "C", which refers to the half of the hexagonal screw head. The "K" has been replaced by a "C" to emphasize the reference to the screw head. All modules are mechanically fixed with M2 screws with a diameter of 2 mm.

The expansion bus interface is designed to create an open ecosystem of function modules for high-performance peripheral connectivity. Its main focus is on supporting FPGA and FPGA SoC devices from all major manufacturers.

Visit **cruvi.com** for more information

What is CRUVI?



CR00140 Industrial Motor controller board with CRUVI connector

This board allows motor control applications with any CRUVI carrier that supports at least one HS slot. IO voltage range supported 1.2V to 3.3V. There are total 4 phases available for either one 3 phase or two 2 phase motors. Pin headers are available for rotation sensor connections. There is current measurement on two phases and DC link voltage.

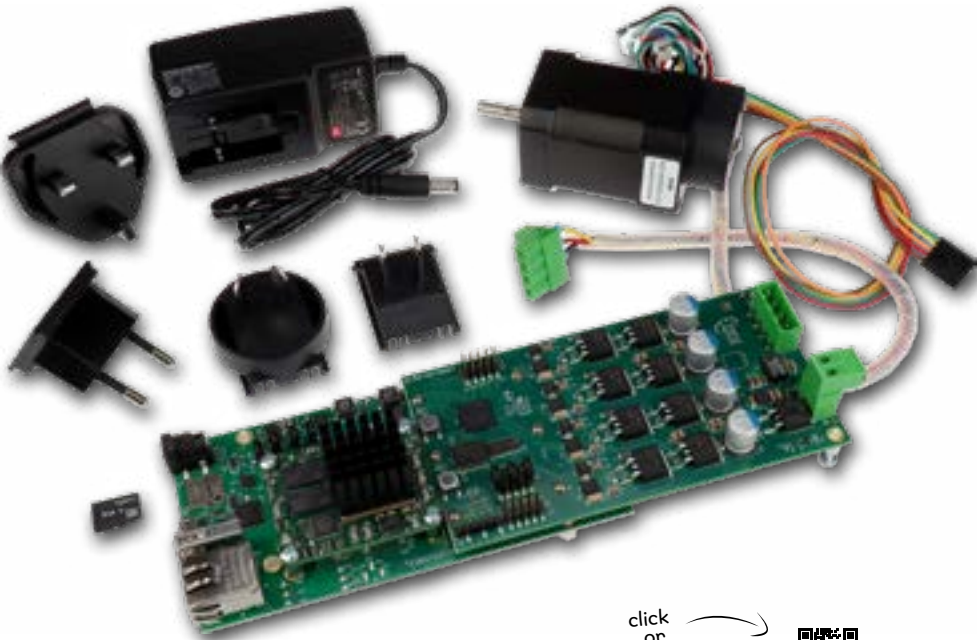
	FMC LPC	SYZYGY	CRUVI HS	Pmod	CRUVI LS
Single ended I/O	68	28	37 (28 + 9)	8	8
Differential I/O pairs	36	10	12	-	-
Management I2C	I2C	SmartVIO	I2C/SMBUS	No	I2C (shared)
Mounting hole(s)	Yes	2 one side	1..6	No	1..6
Power supply	Adj., 3.3V, 12V	Adj., 3.3V, 5V	Adj., 3.3V, 5V	3.3V	3.3V, 5V
License	VITA \$\$\$	Free	Free	Free	Free

CRUVI Baseboards



	CR00100	CR00103
Device Family	MAX® 10	Certus-NX
Device List	10M08	LFD21X-40
Form Factor	4.5 x 5.7 cm	4.5 x 5.7 cm
Interface / Connectors	CRUVI (1 x HS, 1 x LS), 2 x 34 Pin header	CRUVI (2 x 34 Pin Header, 1 x High Speed 60 Pin Header, 1 x Low Speed 12 Pin Header), micro USB
max. SDRAM	8 MB	16 MB HyperRAM
Flash	-	32 MB
Ethernet / USB	- / USB 2.0	USB 2.0 UART/FIFO
Total I/Os	37 + 8	178
Other Features	User push button, LEDs	USB to FIFO FTDI (JTAG/GPIO), user LEDs, push buttons

CRUVI Development Kit & Board



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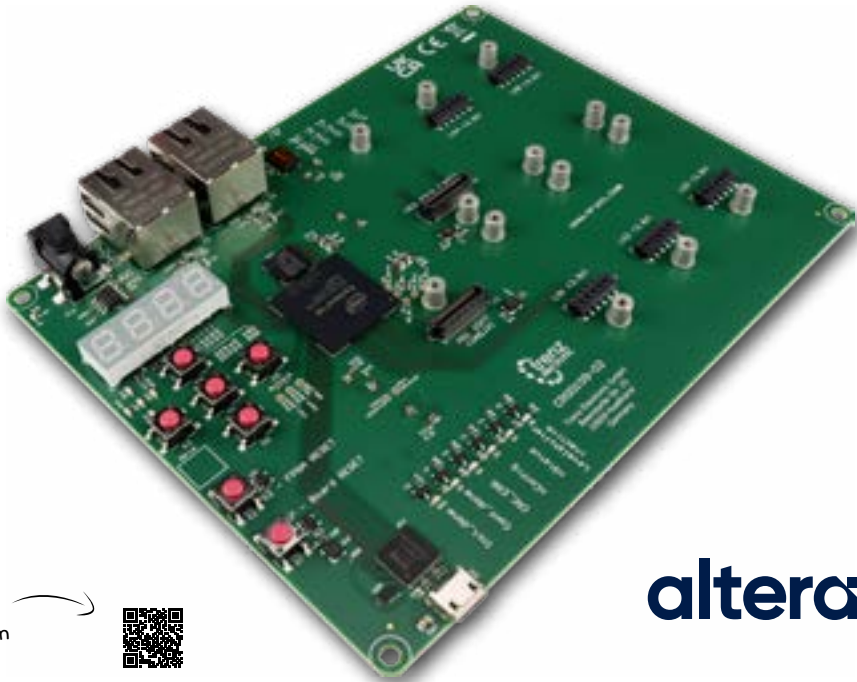


	CR00109
Device Family	Cyclone® 10 LP
Device List	Cyclone® 10 LP, 10CL016, 10CL025, 10CL040, 10CL055, 10CL080
Form Factor	11.65 x 15 cm
Connectors	5 x CRUVI LS, CRUVI HS, CRUVI HS & BOOT, 2 x RJ45, micro USB
max. SDRAM	64 MB
Other Features	2 x 10/100 Ethernet PHY, 2 x MAC EEPROM, Oscillator, 4 x 7-Segment-Display, user buttons, user LEDs, status LEDs

CR00140 Motor Control Development Kit:

A CRUVI motor driver module CR00140-02, a carrier board TEB0707 and a MPSoC (TE0820/AMD UltraScale+™) or SoC (TE0720/AMD Zynq™) module including a heat sink. Supplied with a universal plug-in power supply with four adapters, a DC motor including cable for CRUVI CR00140 and an 8 GB microSD card.

CR00140-02-K0A with MPSoC TE0820
CR00140-02-K1A with SoC TE0720



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CRUVI Adapter

Small sizes mezzanine module standard providing option for high speed and ultra low cost modules.

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	CR00025 Pmod to CRUVI low speed Host Slot	CR00026 Signal breakout debug Adapter	CR00200 HS Ethernet PHY Adapter	CR00202 HS Dual Ethernet PHY Adapter	CR00240 HDMI Adapter
On-Board	• Steel spacer • M3-Hole • B2B & Mezzanine connector	• CRUVI HS Host & Device connector • 100 mil pin headers	• CRUVI HS connector • ETH PHY, 25 MHz oscillator	• CRUVI HS connector • 2 x ETH PHY and 25 MHz oscillator	• Serial EEPROM with EUI-48 Node Identity • HDMI/DVI level shifter with active DDC Puffer (PTN3363BSMP)
Memory	-	-	• Serial EEPROM with EUI-48 Node Identity	• 2 x Serial EEPROM with EUI-48 Node Identity	-
Interface	-	-	• CRUVI and RJ45	• CRUVI and 2 x RJ45	• Samtec ST4-30-1.50-L-D-P-TR (Ultra-Fine Pitch Header 60 pins) • HDMI connector
Power	via CRUVI	via CRUVI	via CRUVI	via CRUVI	via CRUVI



CR00045 AP Memory x8 / x16 Xccela PSRAM Board	CR00049 EMMC expansion Module	CR00091 Loopback Adapter	CR00101 FMC to CRUVI Adapter	CR00300 Camera Adapter
- AP Memory IoT RAM (OPI & HP): 256 Mbit x8/x16 1.8V 200 MHz DDR PSRAM - Serial EEPROM with EUI-48 Node Identity	- eMMC: 8 GB 1.8V/ 3.3V eMMC (SDINBDG4-8G-XI2) - Serial EEPROM with EUI-48 Node Identity	25 MHz oscillator (REFCLK) - EEPROM (SMB BUS) - LED indicators for all three power rails and SMB_ALERT	1 x FMC HPC connector 2 x CRUVI HS connectors 4 x Steel Spacer - Altera® MAX@10 FPGA 8kLE and internal Flash, 128 kbit I2C EEPROM - clock generator 100 MHz 2 x LEDs (red, green) 4 x DIP switch	Serial EEPROM with EUI-48 Node Identity
-	-	-	2 x Serial EEPROM with EUI-48 Node Identity	-
1.8V 200 MHz DDR x8 / x16 Xccela PSRAM - I2C	1.8V / 3.3V eMMC 5.1 with HS400 - I2C	-	- CRUVI 2 x RJ45	- Samtec ST4-30-1.50-L-D-P-TR (Ultra-Fine Pitch Header 60 pins) - ZIF FFC/ FPC CSI-2 15 pol camera connector
via CRUVI	via CRUVI	via CRUVI	via CRUVI	via CRUVI

Carrier Boards for 4 x 5 cm TE Modules

The carrier boards are baseboards for 4 x 5 SoMs, which exposes the modules B2B-connector-pins to accessible connectors & provides a whole range of on-board components to test & evaluate Trenz Electronic 4 x 5 SoMs.



TE0701	TE0703	TE0705
• Overvoltage-, undervoltage- and reversed- supply-voltage-protection • Barrel jackc for 12 V power supply • Carrier Board System-Controller CPLD • Mini CameraLink connector • RJ45 Gigabit Ethernet MagJack • FPGA Mezzanine Card (FMC-LPC) connector • USB JTAG- and UART interface with Mini-USB connector • HDMI transmitter with HDMI connector • 8 x user LEDs, 2 x user push buttons, 2 x DIP switch • Pmod connectors, Micro SD card socket and Micro-USB interface	• 2 x VG96 cconnectors (mounting holes and solder pads) • SDIO port expander with voltage-level translation • MicroSD card socket • 4 x user LEDs, 1 x user-push button, 2 x user configurable DIP switches • Mini USB connector (USB JTAG and UART interface) • RJ45 Gigabit Ethernet socket with 4 integrated LEDs • USB host connector • Barrel jack for 5V power supply input • DCDC step-down converter for 3.3V power supply • USB JTAG and UART interface	TE0705 carrier board is a simplified version of the TE0701. It provides a cost-effective way to connect Trenz 4 x 5 modules and connect them to your own circuits. As little as possible has been changed in functionality except the functionality that was removed. Changes from TE0701: • Pmod connectors changed to IDC headers • HDMI removed • CL connector removed • USB connector position changed • 5 pin header support added on both USB interfaces • 12V DC power input connector changed to different type • FMC connector removed and replaced by two dual row 100 mil pin headers

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TE0706	TEB0707
• VG96 connector and 50-pin IDC male connector socket • SDIO port expander with voltage-level translation • MicroSD card socket and a USB type A connector • 1 x user push button, user configurable DIP switch • 2 x RJ45 Gigabit Ethernet MagJack • 1 x Ethernet PHY • Barrel jack for 5V power supply input • DCDC step-down converter for 3.3V power supply • JTAG pins on 12-pin header • 3 x VCCIO selection jumper	TEB0707 is a carrier board for 4x5 Trenz Electronic modules. It provides three high speed and one low speed CRUVI extension connectors. • Altera® Max® 10 FPGA • FTDI FT2223 • Gigabit RJ45 LAN socket • MicroSD card socket, MicroUSB2.0 socket, USB A socket • 6 x user LEDs (3 x green, 3 x red) • 5V input power supply

Carrier Boards for TE Modules – different form factors

Following carrier boards are baseboards for specific Trenz Electronic SoMs, which exposes the module's B2B-connector-pins to accessible connectors & provides a whole range of on-board components to test & evaluate Trenz Electronic SoMs.



	TEBF0808/TEBF0818	TEB0835/TEB0836
Supported SoM	TE0803/0807/0808 & TE0813/0817/0818 MPSoC series	TE0835 & TE0836 RFSoc series
IO Resources / Interface	• USB3.0 with USB3.0 HUB • FMC HPC slot (1.8V max VCCIO) • MicroSD card (bootable) and eMMC (bootable) • PCIe slot - one PCIe lane (16 lane connector) • Fan connectors, PC enclosure, FMC fan • Altera® front panel- and HDA audio-connector • CAN FD transceiver (10 pin IDC connector) • Displayport single lane • 1x SATA connector • Dual SFP+ • Gigabit Ethernet RJ45 • 1x Samtec FireFly (4GT lanes bidir.) • 1x Samtec FireFly connector for reverse loopback • 20 pins ARM JTAG connector (PS JTAG0)	• 21x UMCC connectors • 6x SMA connectors • 2x Micro USB2.0 • RJ45 LAN socket • Micro SD card socket • 2x UEC5 connectors • 2x UCC8 connectors • PCIe x8 card • 2x Samtec Razor Beam SS5 (2 x 80 pol) Board to Board connectors
Onboard	-	• Programmable clock generator • I2C switch IC • 6x user green LEDs • 16x RF transformation • Reset push button • Temperature sensor • FT2232H FTDI • SDIO port expander • 2x DIP switch • Pin headers • PCIe 6 connector
Power Supply	ATX power supply connector (12 V only supply required) Optional 12V standard power plug	12 V input supply
Dimension	Mini-ITX form factor, 17 x 17 cm	10.66 x 10.66 cm



	TEB0865	TEB0955
Supportet SoM	TE0865 MPSoC module	TE0955 AI Edge module
B2B Connector	4x B2B Samtec ADF6-60-03.5-L-4-2-FR	Samtec ADF B2B connectors: 2x 240 pin
IO Resources / Interface	• 1x stacked zQSFP+ (2x zQSFP+) • 2x stacked SFP+ (4x SFP+) • Display Port TX 2 Lanes • 1x RJ45 stacked with 2x USB3.0 Type A • 1x Push-Push microSD • 2x FMC+ (16x DP + 18x LA) • 1x FMC (8x DP + 34x LA) • M.2 SSD Socket Connector Key M PCIe • 2x LS CRUVI • 1x HS CRUVI • 2x GT CRUVI • MIPI CSI-2 4 Lanes (22 pins connector) • JTAG via USB Type C (FTDI FT2232H) • 1x Samtec FireFly (4 Lanes) • 1x USB Type E (Assembly option)	• QSFP, 4x Transceivers • M.2 Key M, 4x Transceivers (2280 default, option: 2260, 2242, 2230) • 2x CRUVI HS (MIPI ready, 4x 4 Lane MIPI) • 1x CRUVI LS • 1x GB Ethernet • 1x micro SD 3.0 slot • 1x USB-C (USB 2.0, dual role) • 1x USB-C (USB 2.0, JTAG + UART) • 1x CAN • optional: several pin headers for I2C, UART, LEDs, RST Buttons, MIO GPIOs
Clock Source	• 2x PLL SI5338A-B-GMR	• I2C programmable MGT Clock (default: 156.25MHz) • PCIe common clock 100MHz • optional: fixed MGT Clock • optional: I2C programmable MGT Clock
Onboard, RAM / Storage	• 1x 128K EEPROM 24LC128-I/ST • 2x 8K EEPROM M93C66-RMC6TG • 2x 512K EEPROM CAT24C512WI-GT3 • 5x DIP Switches • 7x Push Buttons • 27x Green LEDs + 4x Red Leds	• FTDI USB to JTAG + UART bridge • CAN Transceiver • Boot Mode Dips (4x) • Reset Buttons
System Controller	Altera MAX 10 FPGA 10M08SAU169I7G	-
Power Supply	12V Input Supply Voltage	12 V (2.1mm barrel connector)
Dimension	23.1 x 21.3 cm	10.5 x 15 cm

Carrier Boards for TE Modules – different form factors



supported
SoM



	TEB0100	TEB0187
Supportet SoM	AMD Ultrascale+ RFSoc KRM-2ZUXXDR	TEI0187 (Agilex 5 E-Series)
B2B Connector	2x ADF6-60	-
IO Resources / Interface	- Transceivers - Connectors	- QSF: 4 GT Transceiver (up to 28Gbps) 2x SFP+ - PCIe x4 connector (Gen3/Gen4) 1x CRUVI GT: 4 GT Transceiver (up to 28Gbps) 2x CRUVI HS: each optimized for x2 CSI-2/DSI-2 (4 Lane) 3x CRUVI LS 3x CSI-2 connector optimized for camera, 4 lane MIPI - FMC: 8 GT Transceiver, 34 LA diff pairs (max 1.3VIO), 8 HA diff pairs (max 1.3VIO)
Clock Source	- LMK04828B - Clock synchronization inputs and outputs (vertical SMP connectors on PCB)	-
Onboard, RAM / Storage	- MIO Peripherals Board - NVMe Adapter Board - Edge PCIe x8 connector	- USB 3.1 (type C connector) - USB JTAG + UART type C connector - USB UART type C connector + PD function (12 V) 2x Gigabit Ethernet RJ45 (1x on Board / 1x on SoM) - HDMI - SSD M.2 PCIe x1 (Gen3/Gen4) 12-output clock source (PLL) - LEDs, temperature sensor, dip switches - MicroSD card (primary boot option) - eMMC (secondary boot option), Data width: 4bit, size: def. 8GB - EEPROM with MAC-address
System Controller	EFM8BB31F64G -2 pcs.	-
Power Supply	12 V power supply, compatible with ATX or 2.5 mm Power Jack	12 V
Dimension	PCIe Gen 4 (11.2 x 25.4 cm)	16 x 16 cm



TEB0716	TEB0729	AMB0010
TE0716	TE0729	AM0010
2x Berkstak 120 Pos. 0.8mm	2x B2B Connector BSE (120 Pins)	2x ADF6
• 12x diff. ADC (,2 bit, 2 MSPS, 2,54mm pin header) • 53x diff. pairs (106 x single ended, 2,54mm pin header) • 1x Gigabit Ethernet • 1x CRUVI LS • 2x optional SMA • 1x micro USB-OTG • TE0790 XMOD Header	• 2x VG96 Connector • 3x RJ45 Connector • microSD Card Receptable • USB Receptable: • Variant A: USB 2.0 Standard-A Receptable • Variant B: USB 2.0 Micro-AB Receptable • 3x 5 pin Pin Header	• 1x RJ45 LAN connector • XMOD (JTAG/UART to USB) • UART Header • I2C Header • Loopbacks for GTHs, IOs, GPIOs
-	-	-
• 12x Input buffer for ADC	• 2x EEPROM • XMOD (TE0790) • DIP Switch • Push Button • Red LED	• Clock Buffer • Oscillator • 4x User dip switch • 4x User LED • microSD card socket • USB connector
-	-	-
5 V 2.1 mm Barrel Jack	5 V Power supply via power jack	12 V
10 x 15 cm	10 x 10.77 cm	12.8 x 10.6 cm

Trenz Electronic Starter Kits | Pre-assembled and ready-to-use

In general our Starter Kits contain a Trenz Electronic micromodule with a pre-assembled heat sink mounted on a Trenz Electronic baseboard. The TE08xx series modules are build in a black Core V1 Mini-ITX enclosure. All this provided with a fitting power supply including different adapters, a microSD card, a USB cable plus screws and bolts. Different module variants can be integrated on request.

	Starter Kit 720 / 820	Starter Kit 729	Starter Kit 813	Starter Kit 817	Starter Kit 818
Module	TE0720	TE0729	TE0813	TE0817	TE0818
FPGA	AMD Zynq™ 7020	AMD Zynq™ 7020	AMD Zynq™ UltraScale+™	AMD Zynq™ UltraScale+™	AMD Zynq™ UltraScale+™
Baseboard	TE0703	TEB0729	TEBF0818	TEBF0818	TEBF0818
Enclosure	-	-	Core V1 Mini-ITX	Core V1 Mini-ITX	Core V1 Mini-ITX
Power Supply	Universal power supply unit	Universal power supply unit	Be Quiet! 400W ATX power supply	Be Quiet! 400W ATX power supply	Be Quiet! 400W ATX power supply
Heat Sink	Heat sink for TE0720, spring-loaded embedded	KK729-03 TE custom built	SuperGRIP	SuperGRIP	SuperGRIP
USB Cable	✓	✓	✓	✓	✓
MicroSD Card	✓	✓	✓	✓	✓
Screws & Bolts	✓	✓	✓	✓	✓

Starter Kit
720 / 820



Starter Kit 729



Starter Kit 81x

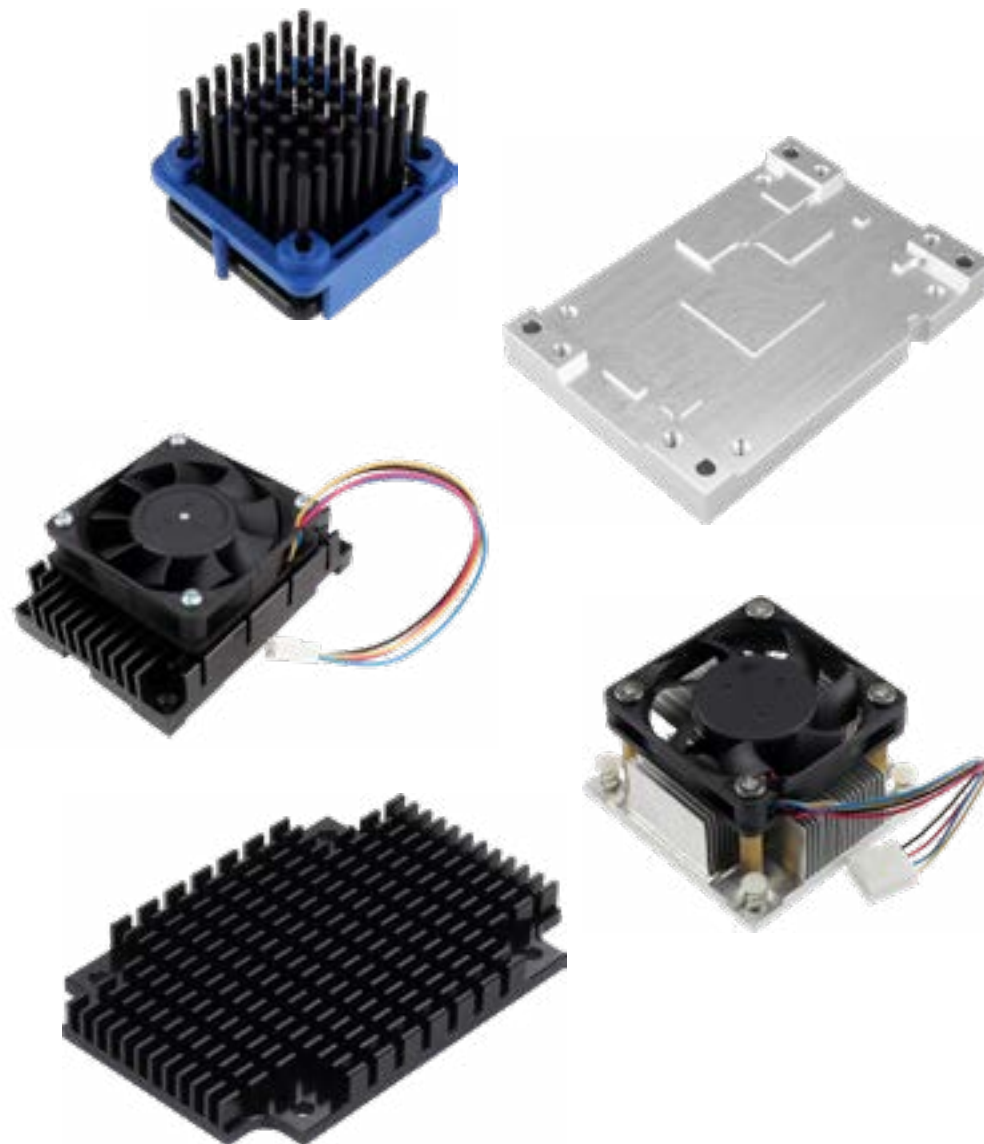


Photo shows
similar product.

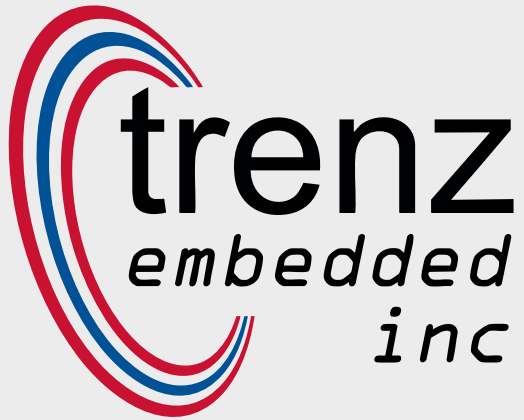
Cooling Solutions | for Trenz Electronic Modules

The individual cooling solutions from Trenz Electronic are required for efficient and effective cooling of the modules and serve to ensure the long-term functional reliability of the systems. The product portfolio includes both active and passive cooling solutions.

TE Series	Article Number
TE0600	26920
TE0710	26925
TE0712 / TE0713	26924
TE0714	KK0714
TE0715	26923
TE0720	33337
TE0724	30829
TE0729	KK0729
TE0741	33013, 33866
TE0745	KK0745
TE0803 / TE0813	KK0803, KK0813, 29665
TE0807 / TE0817	KK0807 KK0817
TE0808 / TE0818	KK0808, KK0818, 29664
TE0820 / TE0821 / TE0823	33338
TE0835	KK0835
TE0841	34323
TE0865	KK0865
TE0950	34097
AM0010	34937
TEB0911, TEF1001	25130
Heat Spreader Extension	34314



Partners & Collaborations.



Trenz Electronic's North American Manufacturer Representative

Founded in 2025, Trenz Embedded Inc. strengthens Trenz Electronic's presence in North America by providing a local point of contact for communication, coordination, and customer support. Our proximity enables faster responses, smoother project planning, and a clearer understanding of customer needs – all without altering or handling any Trenz Electronic products.

Our Role

- Direct communication conduit to the engineering and operations teams in Germany
- Pre sales technical guidance, including helping customers identify suitable modules and services
- Project coordination and design phase support, such as facilitating reviews and relaying technical feedback
- Operational liaison services, including supply chain coordination, lead time discussions, and cost down option exploration
- Coordination with local distribution partners, including project handover from design-in to series production and regional sales support

Our mission is to ensure North American customers receive timely information, expert guidance, and seamless access to Trenz Electronic's capabilities.

Contact

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+1 (425) 532 6720



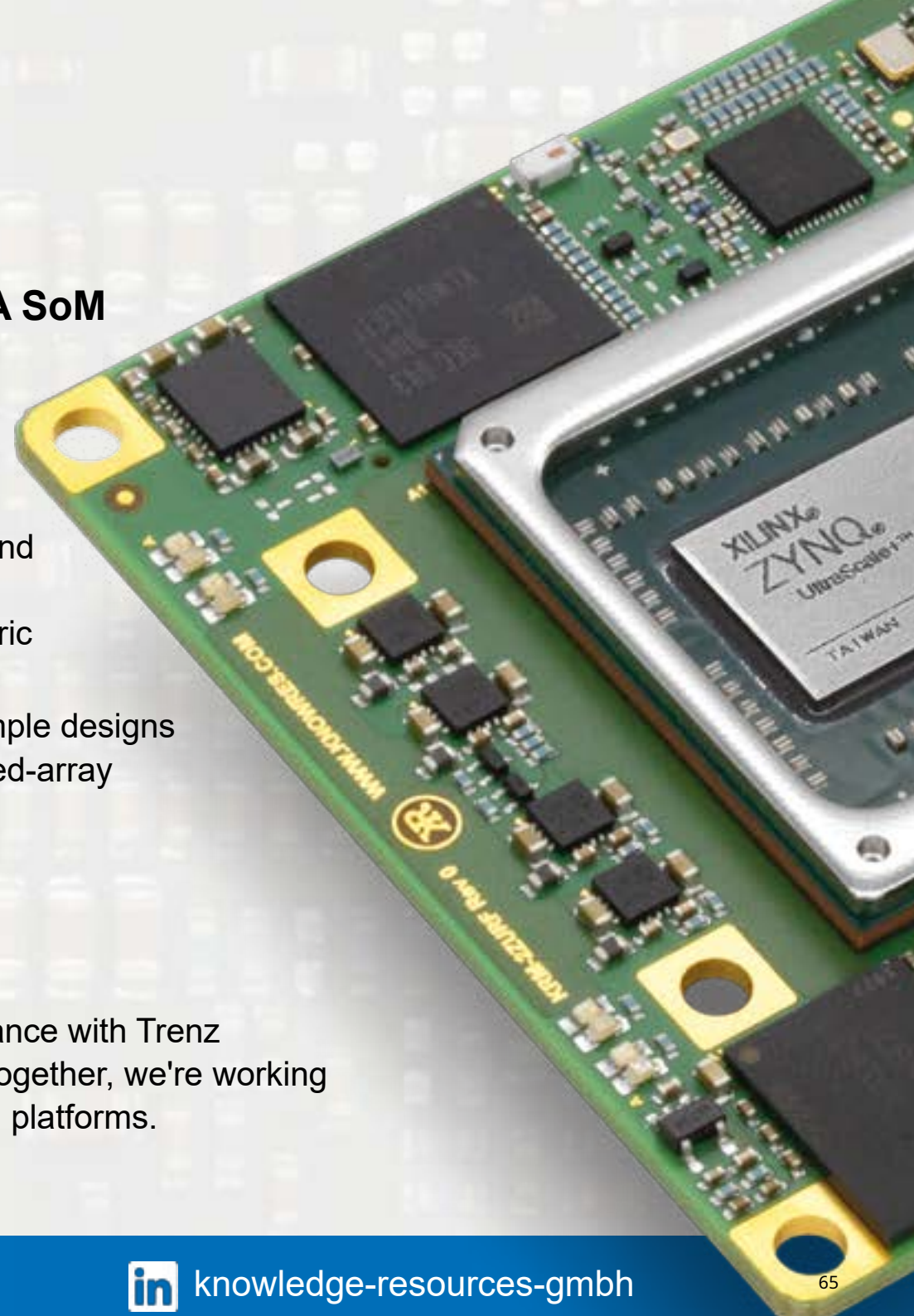
KNOWLEDGE RESOURCES
SWITZERLAND GMBH

Knowledge Resources is a sophisticated FPGA SoM vendor with a broad offering for HPC, RF, and industrial applications. Our RFSoc modules provide:

- Excellent RF performance
- Robust design, proven with multiple deployments in LEO and thousands shipped since 2020
- The highest memory bandwidth - most modules' FPGA fabric includes two 64-bit RAM interfaces
- Flexible and modular evaluation kits with easy-to-use example designs
- Unique features to support multi-module systems for phased-array designs

Knowledge Resources and Trenz Electronic: A Strategic Alliance

The team at Knowledge Resources is pleased to join an alliance with Trenz Electronic to strengthen the European FPGA SoM market. Together, we're working to build a complementary offering of modules and evaluation platforms.



Sales, Support, and Distribution

- **USA Distributor** with volume discounting and module customization
- **Net30 Invoicing** for most public companies
- **Approved Supplier** to the majority of defense contractors

 **USA-BASED 100% US CITIZENS | ITAR/CMMC COMPLIANT | US-BASED ENGINEERING SUPPORT**



EXPERT DESIGN SERVICES

Interfacing at 1 to 100+ Gb/s

- **Networking:** 1G, 10G, 25G, 100G
- **Interfacing:** RF, ADC, MGT, MIPI, LVDS
- **Memory/Host Interfacing:** DMA, PCIe

Computing at 1 to 100+ Gb/s

- UDP/IP and Ethernet RX/TX Cores
- Image Processing/Computer Vision
- RF and Analog Signal Processing

Host Interfacing

- Custom NIC Design
- PCIe Interface
- RDMA

FINISH FASTER

Reference Designs

- Ethernet – 10G/25G Ethernet RX/TX
- AI – Imager Classification
- Cameras – MIPI Camera Interface
- RFSoc – RF Analyzer, PCIe Interface
- Tracking – Laser Point Tracker

IP Cores

- Camera Interfacing
- Image Processing
- UDP/IP Sender/Receiver
- TSN Bridge, TSN Endpoint
- Redundant Ethernet HSR/PRP

Custom System Design

- Design Upgrading/Conversion
- Software-to-Hardware Acceleration
- IP Integration
- HW/SW Codesign, Linux, Software
- Turnkey System Design

CONTACT US TODAY!

Quotes and Free Design Consultation

Dr. Ray Hoare | info@ConcurrentEDA.com | 1-412-687-8800



PLC2 und Trenz Electronic bündeln ihre Kompetenzen, um Kunden entlang der gesamten Entwicklungskette leistungsfähige und zugleich risikoarme Lösungen anzubieten. Während Trenz Electronic seit vielen Jahren für hochwertige Embedded-Hardware, System-on-Module und Trägerboards steht, ergänzt PLC2 diese Expertise durch umfassende Entwicklungs- und Designleistungen mit starkem Fokus auf kundenspezifische Anpassungen.

Im Mittelpunkt der Zusammenarbeit steht ein klar strukturierter Entwicklungsansatz: Projekte beginnen häufig auf Basis bewährter SoM-Plattformen. Diese ermöglichen einen schnellen Einstieg, redu-

zieren technische Risiken und schaffen eine belastbare Grundlage für spätere Produktvarianten. Auch werden SoM-Boards häufig und gerne als risikoarme Lösung in Produkten im mittleren Stückzahlbereich eingesetzt. PLC2 verfügt über langjährige Erfahrung in der Arbeit mit einer Vielzahl von Trenz-Modulen – von etablierten Plattformen wie dem TE0724 mit AMD Zynq 7010/7020 bis hin zu aktuellen Hochleistungsarchitekturen wie dem TE0950 mit AMD Versal™ AI (Edge) – und setzt dieses Know-how gezielt in Kundenprojekten ein. Ein besonderer Mehrwert der Partnerschaft liegt in der frühen und engen Abstimmung beider Unternehmen. Bereits in frühen Entwicklungs-

phasen wird gemeinsam darauf geachtet, dass Architekturentscheidungen, Designparameter und Schnittstellen konsequent auf die Anforderungen einer späteren Serienfertigung ausgerichtet sind. Dadurch lassen sich spätere Anpassungen minimieren, Entwicklungszeiten verkürzen und die Überführung in die Produktion deutlich effizienter gestalten.

Maßgeschneiderte Lösungen auf verlässlicher Basis

Kunden profitieren von einem nahtlosen Zusammenspiel aus standardisierter, zuverlässiger Hardware und individuell angepasstem Design. Die Kombination aus Trenz Electronics Hardwarekompetenz und PLC2s Entwicklungs- und Systemverständnis schafft Lösungen, die nicht nur technisch überzeugen, sondern auch wirtschaftlich und langfristig tragfähig sind.

Mit dieser Partnerschaft bieten PLC2 und Trenz Electronic eine solide Basis für innovative Embedded-Systeme – von der ersten Idee bis zur Serienreife.

Bereit für die Umsetzung?

Wir begleiten Sie gerne bei der Realisierung.

Scannen Sie den Code oder besuchen Sie uns unter: plc2.com



TimeTagger – low-cost, mid-resolution time-to-digital converter

With a time resolution in a range of a few 100 ps and an even smaller jitter, the TimeTagger4 features an enormous price-value ratio. The various device variants offer bin sizes between 100 and 800 ps in desktop, PCIe board or module form factor.

TimeTaggers are low-cost, mid-resolution time-to-digital converters ideally suitable in applications that do not require the highest resolution, but high data acquisition rates and the lowest multiple-hit dead time. All variants of these high-bandwidth, low-cost, common-start TDCs are available as PCIe-board, desktop-unit or as space-saving TDC modules which can be installed via board-to-board connectors with minimal hardware effort.

The threshold discriminators can use positive or negative thresholds with configurable voltage. This allows you to use the xTDC with a wide range of detectors or constant fraction discriminators (CFD). All inputs can also be used to output periodic pulse patterns to control your setup - the exact timing of these is measured by the TDC.

Typical applications:

- TOF Mass Spectrometry
- Quantum Sensing
- Quantum Key Distribution
- Optical Time-Domain Deflectometry
- Time-Correlated Single Photon Counting
- Fluorescence-Lifetime Imaging Microscopy
- Fluorescence Lifetime Correlation Spectroscopy
- Phase Shift Measurements
- Hyperspectral Imaging
- Ultra-High-Resolution LIDAR



TimeTagger – Data	
Optimized for	low-cost
TDC channels	1 start & 4 stop channels
Connectors	5 x LEMO 00
Bin size (depending on version)	800/400/200/100 ps
Double pulse resolution	2 bins
Multihit	8000x per start event
Dead time between groups	none
Readout rate	60 MHits/s total; 40 MHits/s per channel
Timestamp range	1.67 ms/430 ms extended
Number of boards that can be synced	Synchronization not supported
Common start/stop	yes/no
Readout interface	PCIe gen. 2 @ 400 MB/s
Time base	250 ppb on-board
Linux support available	yes



Scan for more information



The compact (approximately 30x40x5 mm) TimeTagger TDC modules enable a reduction in the space required for integrated picosecond time measurement units.



Ndigo6G-12: Versatile pulse acquisition platform - ADC

The Ndigo6G-12 is a hybrid ADC/TDC solution for the acquisition of short pulses. It builds on the proven Ndigo5G-10 platform, but sets new standards in terms of performance and flexibility.

The Ndigo6G-12 is particularly well-suited for time-of-flight applications like LIDAR or TOF mass spectrometry. Pulse arrival times can be measured with an accuracy down to 5 ps in combination with information on pulse shape such as area or amplitude.

Four channels at 1.6 Gsps with 12-bit resolution can be recorded independently or combined to two or one channel(s) with a higher dynamic range of up to 6.4 Gsps. The Ndigo6G-12 comprises, in addition, four TDC channels with a resolution of 13 ps.

cronologic will support you with drivers for Windows and Linux.

Applications:

- All applications requiring ultra-high-speed data acquisition.



Ndigo6G-12 - Data	
Optimized for	TOF applications
ADC channels	4
TDC channels	4
Gating channels	2
Connectors	10x LEMO 00
Sample rate single channel	6400 Msps
Sample rate multi channel	1600 Msps
Resolution	12 bits
TDC double pulse resolution	typically 5 ns
TDC bin size	13 ps
Multihit	unlimited
Dead time between groups	none
TDC readout rate	30 MHits/s; 11.6 MHits/s
ADC readout rate	approx. 5200 MByte/s
Timestamp range	106 d
Common start/stop	yes/yes
Readout interface	PCIe3 x8
Time base	50 ppb on board or external 10 MHz clock
On-board calibration data storage	yes
Adjustable trigger windows	yes
Overlapping events possible	yes
Easy to use Windows C API	yes
In-system firmware update	yes
Linux support available	yes

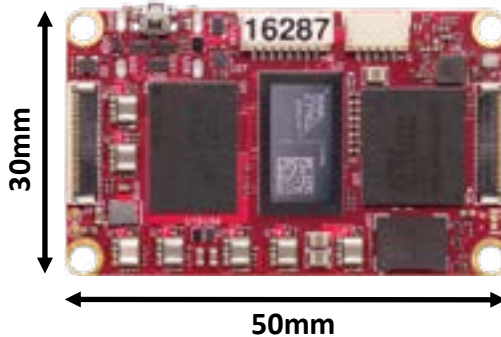
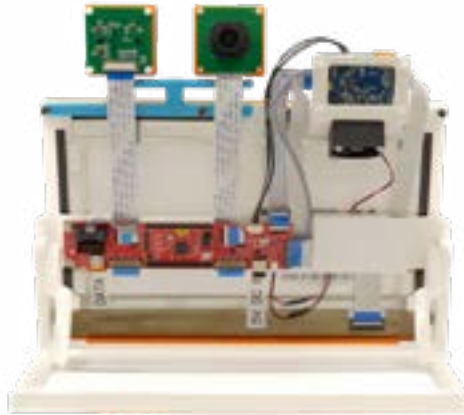


Scan for more information

Sundance Multiprocessor Technology Ltd.

VCS³ - 3D Kit

Embedded Vision Development Platform. This kit is a self-contained hardware platform that houses the Sundance VCS³ Core, two cameras, a screen, and the VCS³ RP2040 converter card.



VCS³ Core actual size



store.sundance.com/VCS3-3D-KIT



The Sundance VCS³ 3D Kit is a compact, ready-to-assemble embedded vision system designed for rapid prototyping, education, and advanced development. Built around the powerful VCS³ Core (AMD Zynq™ UltraScale+™ MPSoC), the kit combines ARM processing with FPGA acceleration for real-time vision and control tasks.

The VCS³ 3D Kit demonstrates the VCS³ Core's compact size and performance in video processing applications.

Measuring just 30mm x 50mm, this tiny workhorse can be placed almost anywhere, opening up the benefits of FPGAs to many more applications.

The VCS³ 3D Kit also includes dual camera modules, a 10.1" high-resolution display, a VCS³ RP2040 co-processor board, and a complete set of 3D-printed mounts, enclosures, and cables, enabling users to quickly assemble a fully functional stereoscopic vision system.

Ideal for machine vision, robotics, sensor fusion, and FPGA-accelerated computing, the VCS³ 3D Kit offers a professional-grade platform in a compact, desktop-friendly form factor — perfect for labs, developers, and innovators pushing beyond traditional single-board computers.

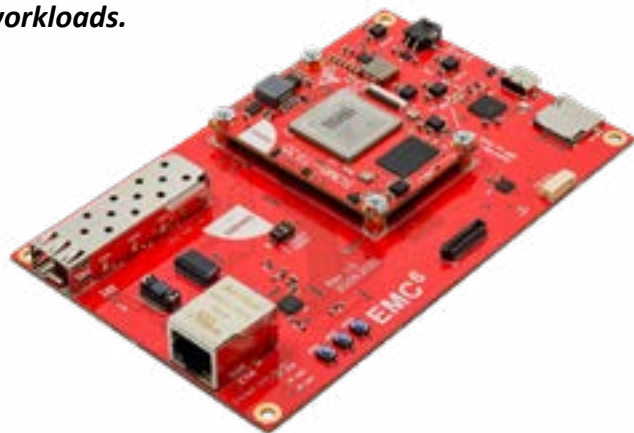
Components included:

- 1x Sundance VCS³ Core
- 1x Sundance VCS³ RP2040 card
- 1x screen (10.1", 1920x1200, 34 pin)
- 2x Raspberry Pi Camera Module 2 (15 pin)
- 1x fan (30mm x 30mm, 5V)
- 1x mini JST 2 pin male connector
- 3D printed holder for the system
- Full cable kit
- Full fixings kit

Sundance Multiprocessor Technology Ltd.

SMT135-C - Ti135 Evaluation Board

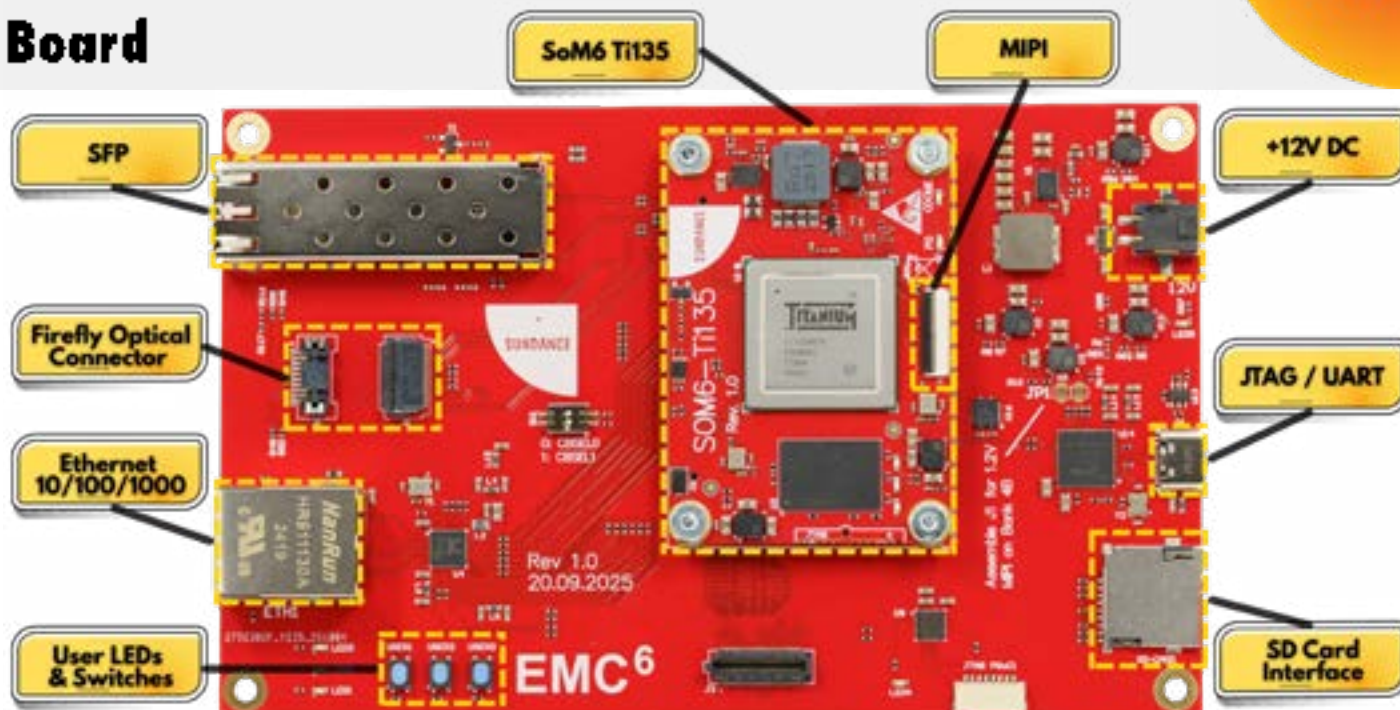
An Efinix Titanium Ti135 Evaluation Board for edge computing, real-time control, and vision-centric workloads.



Interface	Description
RJ45	10/100/1000 Ethernet Interface
SFPK-SL-TR	SFP Interface
USB-C	JTAG and UART via FTDI for the Ti135 FPGA
Firefly PCUO	For Mid-Board Optical Interface
SS4-30-3.00-L-D-K-T-R	8-Lane MIPI TX & RX
TE 2-1445057-2	12V Power Connector
Operating Voltage	12V DC
Supply Current (Running DDR Memory Test)	320mA
Total mass	100g



store.sundance.com/SMT135-C



The SMT135-C Evaluation Board is based on a SoM6 Ti135, a compact, low-power System-on-Module (SoM) built around the Efinix Titanium Ti135 FPGA, in the high-density N676 package.

Designed for advanced embedded applications requiring performance, flexibility, and energy efficiency, the SoM6 Ti135 integrates a rich set of modern features in a form factor that emphasises modularity and interoperability.

The SMT135-C expands on the SoM6's functionality by providing a range of additional I/O options, including a Gigabit Ethernet Interface, SFP Interface, Samtec FireFly Mid-Board Optical Transceiver, SD Card Interface, and the option for 8-Lane MIPI TX and RX operation.

Key SoM Processing and Fabric Features - at the core of the SoM is the Efinix Ti135 FPGA, fabricated on a TSMC 16nm process and featuring the Quantum™ compute fabric.

This fabric includes:

- Up to 129,600 logic elements using eXchangeable Logic and Routing (XLR) cells
- 960 blocks of 10-kbit SRAM (totalling ~9.83 Mbits)
- 480 DSP blocks supporting integer and BFLOAT16 computations
- A quad-core hardened RISC-V processor with full support for RV32IMACFD extensions

These features combine to make the SMT135-C a strong candidate for edge computing, real-time control, and vision-centric workloads.

SUNDANCE

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www.flsiot.com

Haley Technology Co. Ltd.
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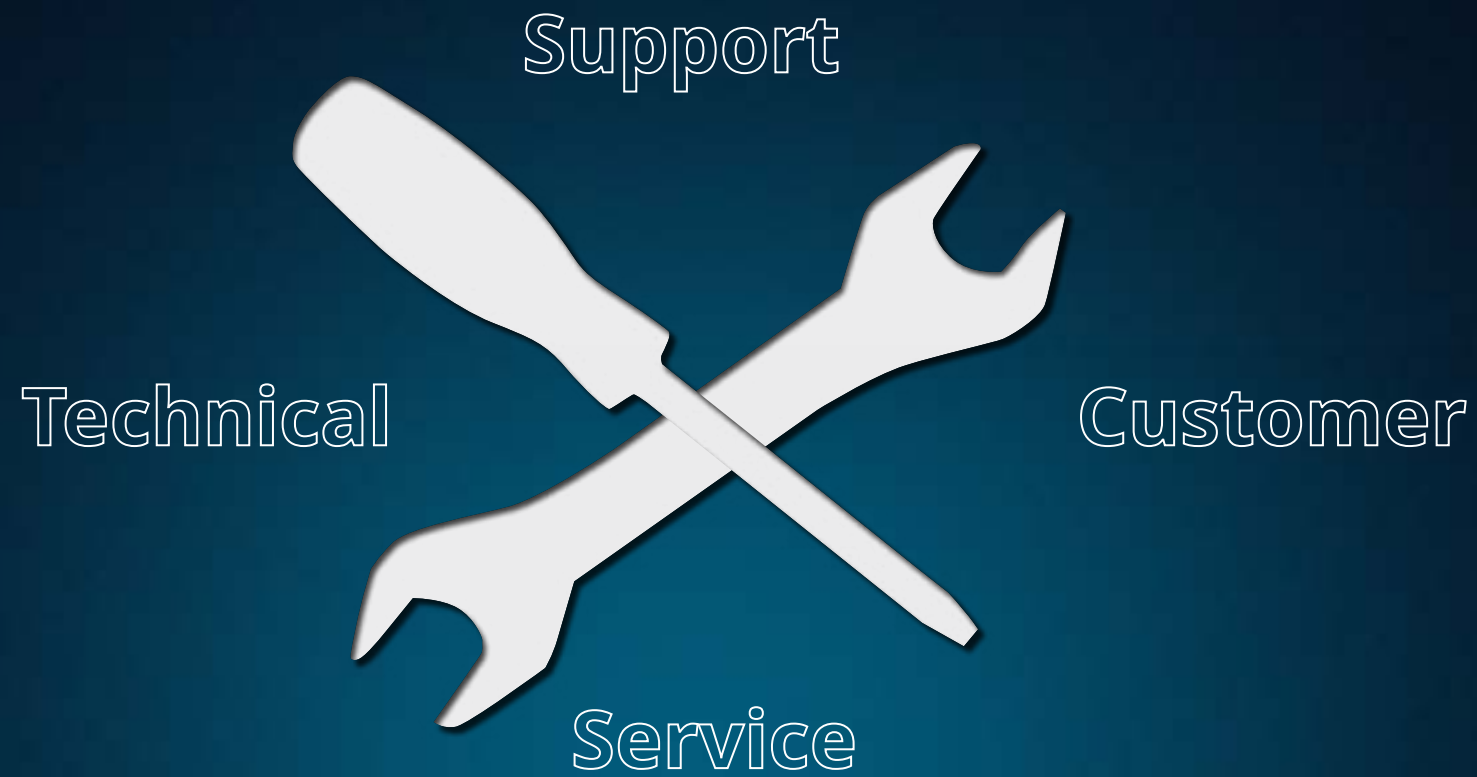
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Forum

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